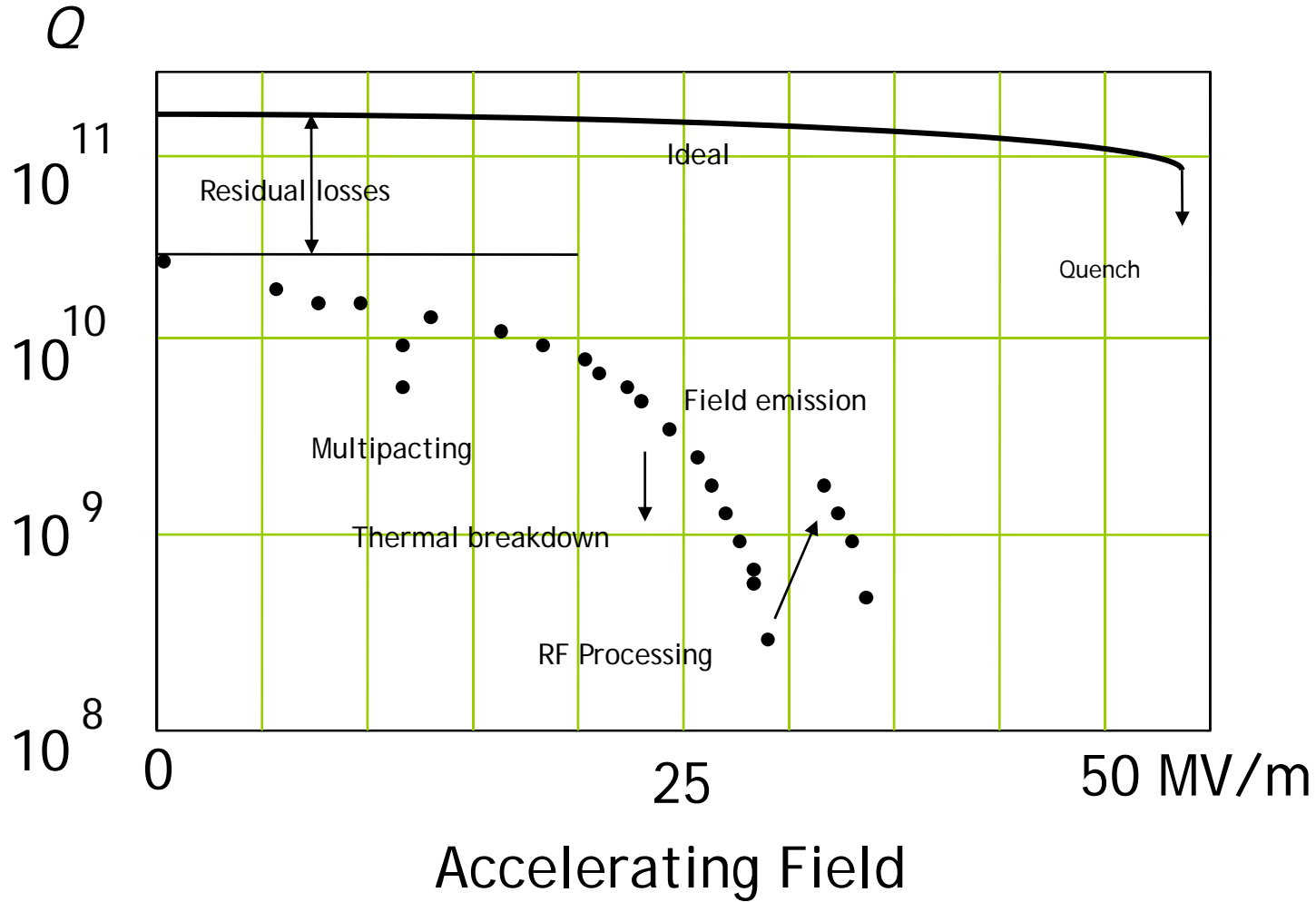


SRF LIMITATIONS

Jean Delayen

Thomas Jefferson National Accelerator Facility
Old Dominion University

The Real World



Characteristics of Residual Surface Resistance

- **No strong temperature dependence**
- **No clear frequency dependence**
- **Not uniformly distributed (can be localized)**
- **Not reproducible**
- **Can be as low as 1 n Ω**
- **Usually between 5 and 30 n Ω**
- **Often reduced by UHV heat treatment above 800C**

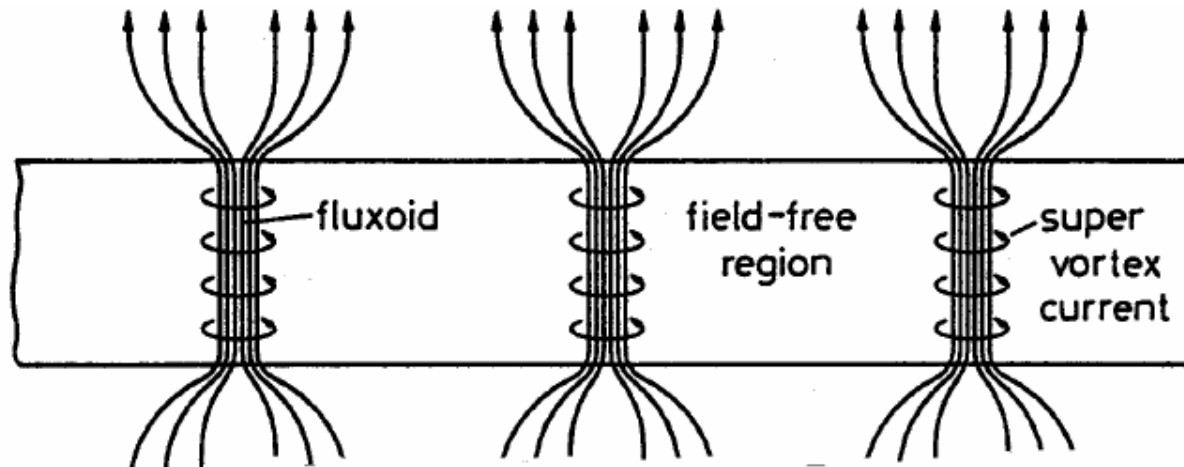
Origin of Residual Surface Resistance

- **Dielectric surface contaminants (gases, chemical residues, dust, adsorbates)**
- **Normal conducting defects, inclusions**
- **Surface imperfections (cracks, scratches, delaminations)**
- **Trapped magnetic flux**
- **Hydride precipitation**
- **Localized electron states (photon absorption)**

Trapped Magnetic Field

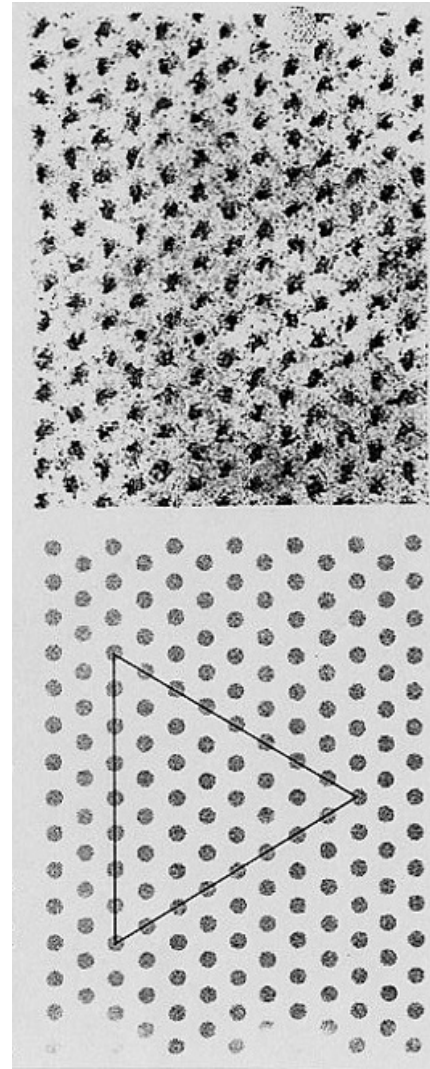
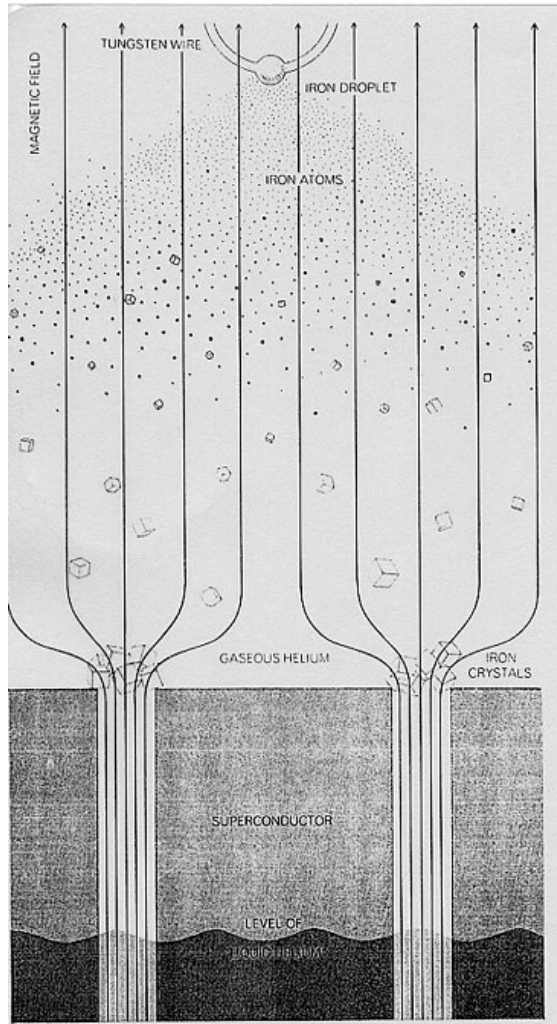
A parallel magnetic field is expelled from a superconductor.

What about a perpendicular magnetic field?



The magnetic field will be concentrated in normal cores where it is equal to the critical field.

Trapped Magnetic Field



Trapped Magnetic Field

A fraction H / H_c of the material will be in the normal state.

This will lead to an effective surface resistance $R_n(H / H_c)$

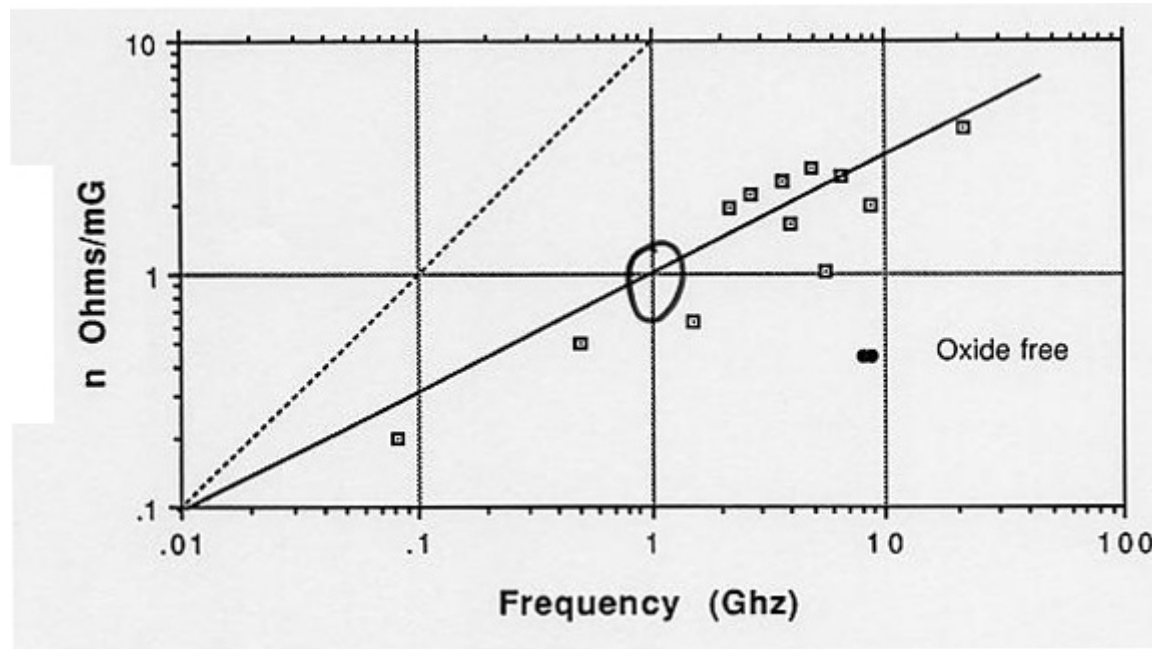
For Nb: $R_{eff} \approx 0.3$ to $1 \text{ n}\Omega/\text{mG}$ around 1 GHz

While a cavity goes through the superconducting transition, the ambient magnetic field cannot be more than a few mG.

The earth's magnetic field must be effectively shielded.

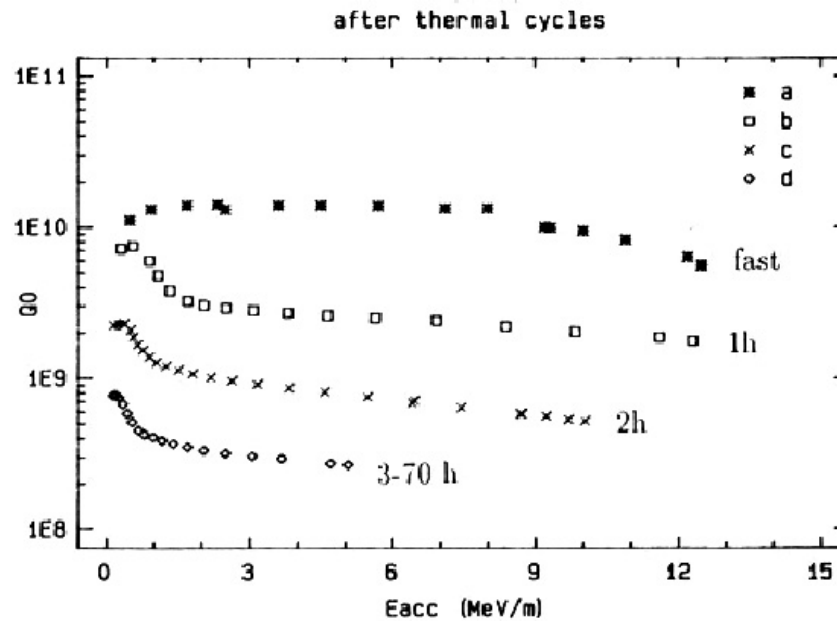
In cavities made of composite materials, thermoelectric currents can cause trapped magnetic field.

Trapped Magnetic Field



Q Disease

Cavities that remain at $\sim 100\text{K}$ for an extended period of time experience a sharp increase of surface resistance



Q Disease

At room temperature, the hydrogen moves freely through niobium

At lower temperature, H precipitates to form a hydride with poor superconducting properties: $T_c=2.8$ K, $H_c=60$ G

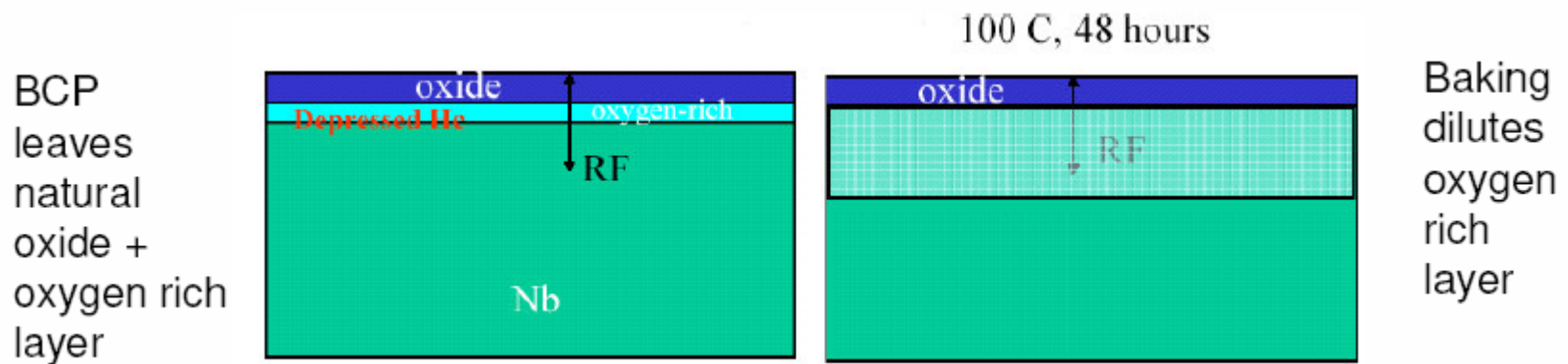
At room temperature the required concentration to form a hydride is 10^3 - 10^4 ppm

At 150K it is <10 ppm

Can be eliminated by baking cavity at 600-800C

High Field Q-Drop

- **Decrease of Q at high field not associated with x-rays**
- **Still an area of investigation**
- **Many models**
 - **Magnetic field related**
 - **Electric field related**
- **Strong indication that it is related to the concentration of oxygen at the surface**
- **Reduced or eliminated by mild baking around 120C**



High Field Q-Drop

Pollution Model

- Important impurities in Nb are O, N, C, H
- A “pollution layer” (1- 10 nm) of high O concentration resides below the oxide (some spotty evidence for this from surface analysis)
- This layer weakens the superconducting properties of the thin layer, e.g., by lowering H_{c1} and H_{sh}
 - Magnetic flux begins to penetrate at lower field, and cause RF losses.
- At 100 C, 48 hours, O diffuses (typically 100 nm)
 - N and C are unlikely to be responsible because these diffuse much more slowly compared to Nb ($\ll 1$ nm)
- Baking dilutes the pollution layer, raising H_{c1} and H_{sh} .

High Field Q-Drop

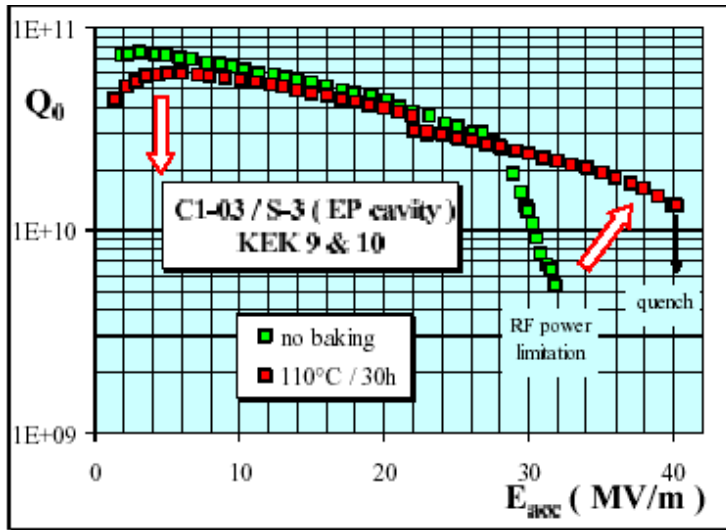
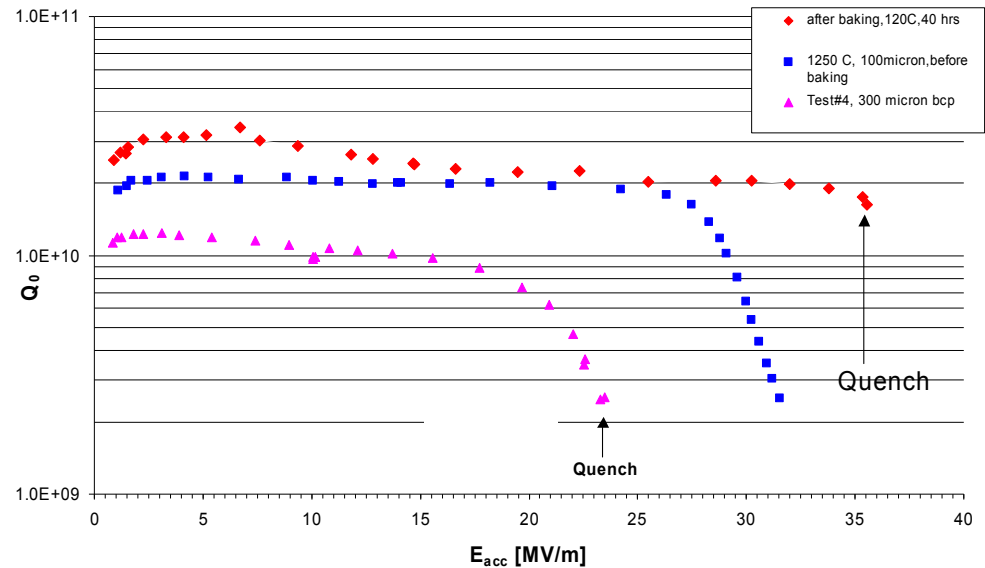
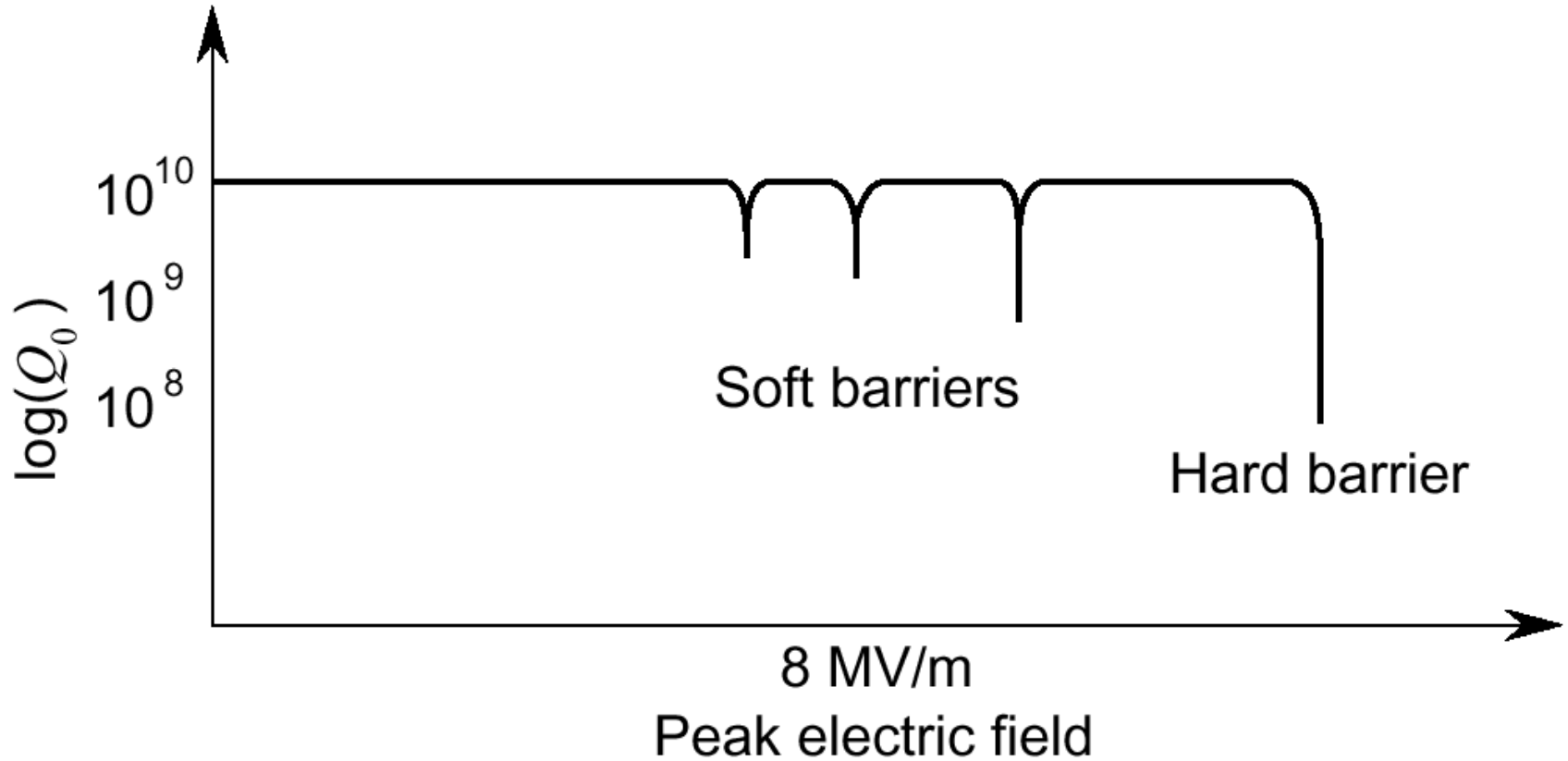


Figure 4: Baking effect on C1-03 Saclay cavity (electropolished and tested at KEK) [9].

CEBAF Single cell cavity Nb/Ta 1162_33/1162_34
 Q_0 vs. E_{acc} ,

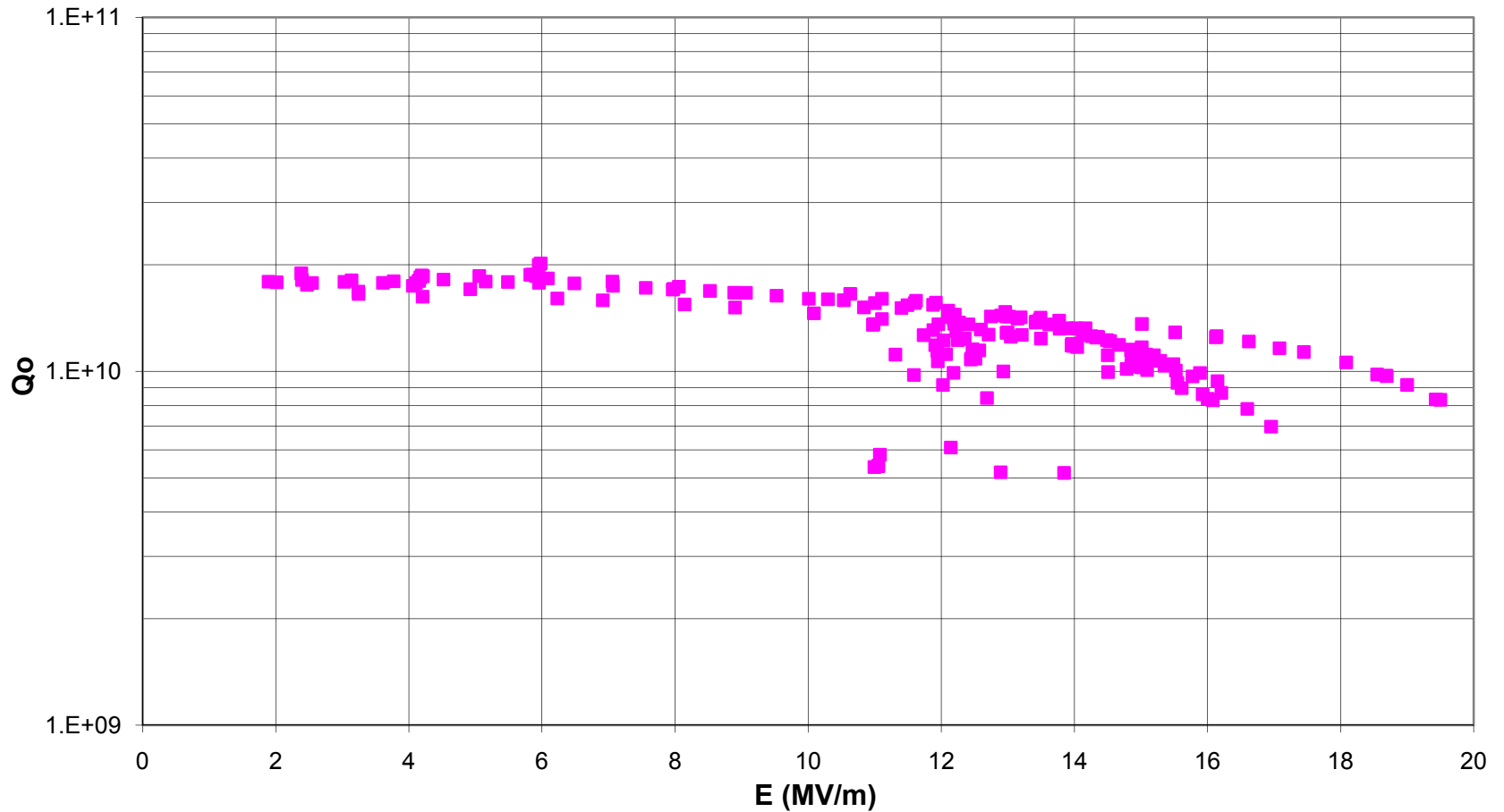


Multipacting



Multipacting

SNS HB54 Qo versus Eacc
Multipacting limited at 16MV/m 5/16/08 cg



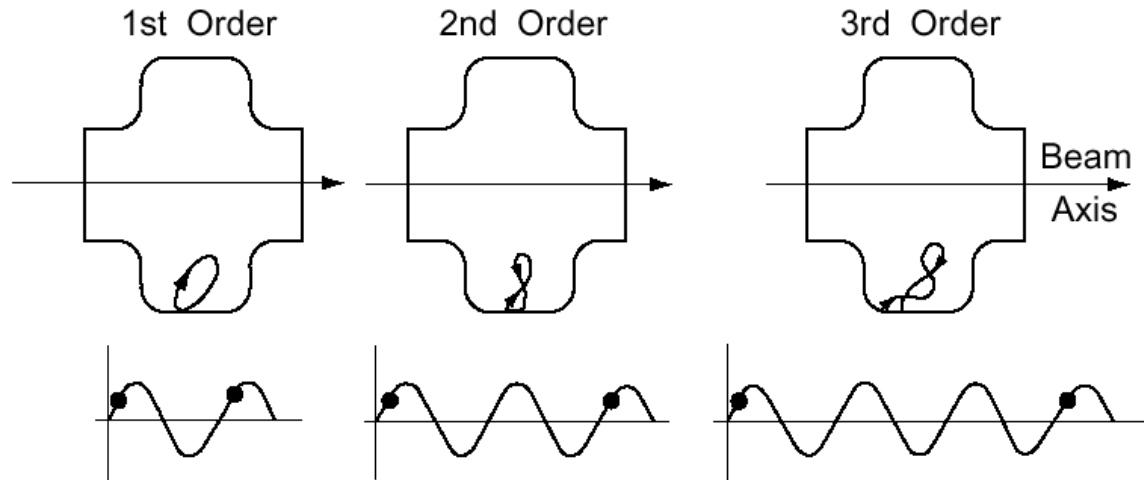
Multipacting

Multipacting is characterized by an exponential growth in the number of electrons in a cavity

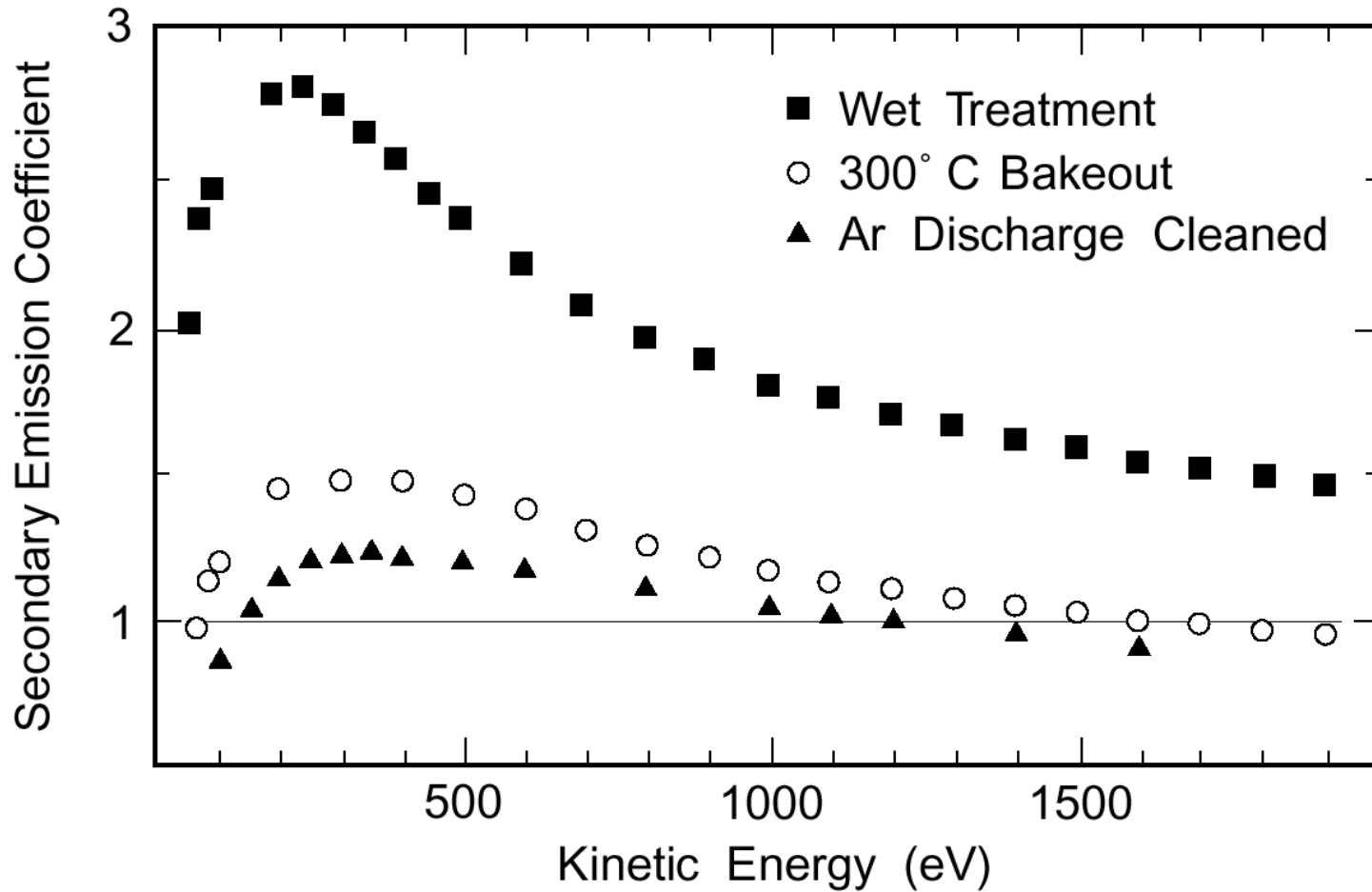
Multipacting requires 2 conditions:

Electron motion is periodic (resonance condition)

Impact energy is such that secondary emission coefficient is >1



Multipacting



Secondary Emission in Niobium

STUDIES OF MULTIPACTING IN AXISYMMETRIC CAVITIES FOR MEDIUM-VELOCITY BEAMS*

W. Hartung

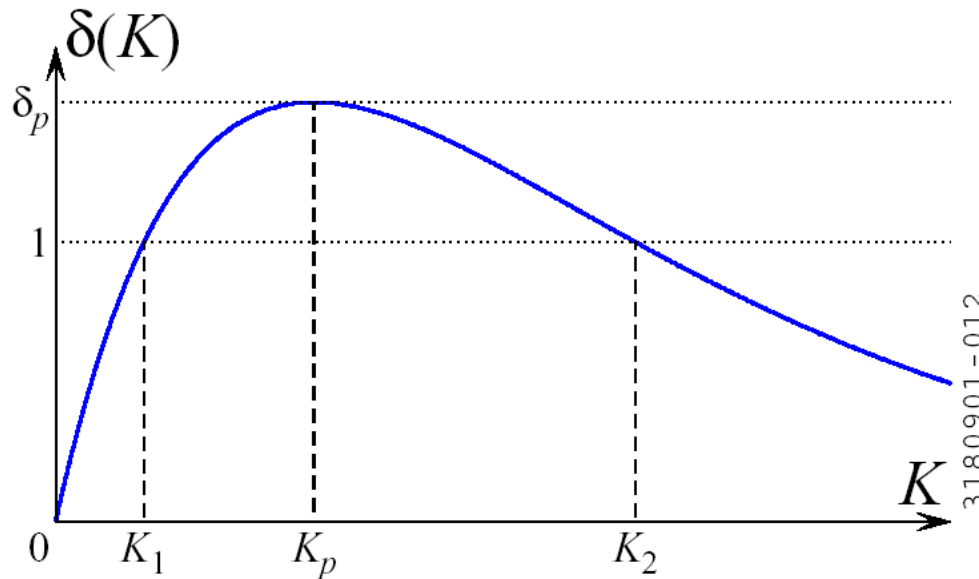
National Superconducting Cyclotron Lab, Michigan State University, East Lansing, Michigan

F. Krawczyk

Los Alamos National Laboratory, Los Alamos, New Mexico

H. Padamsee

Laboratory of Nuclear Studies, Cornell University, Ithaca, New York



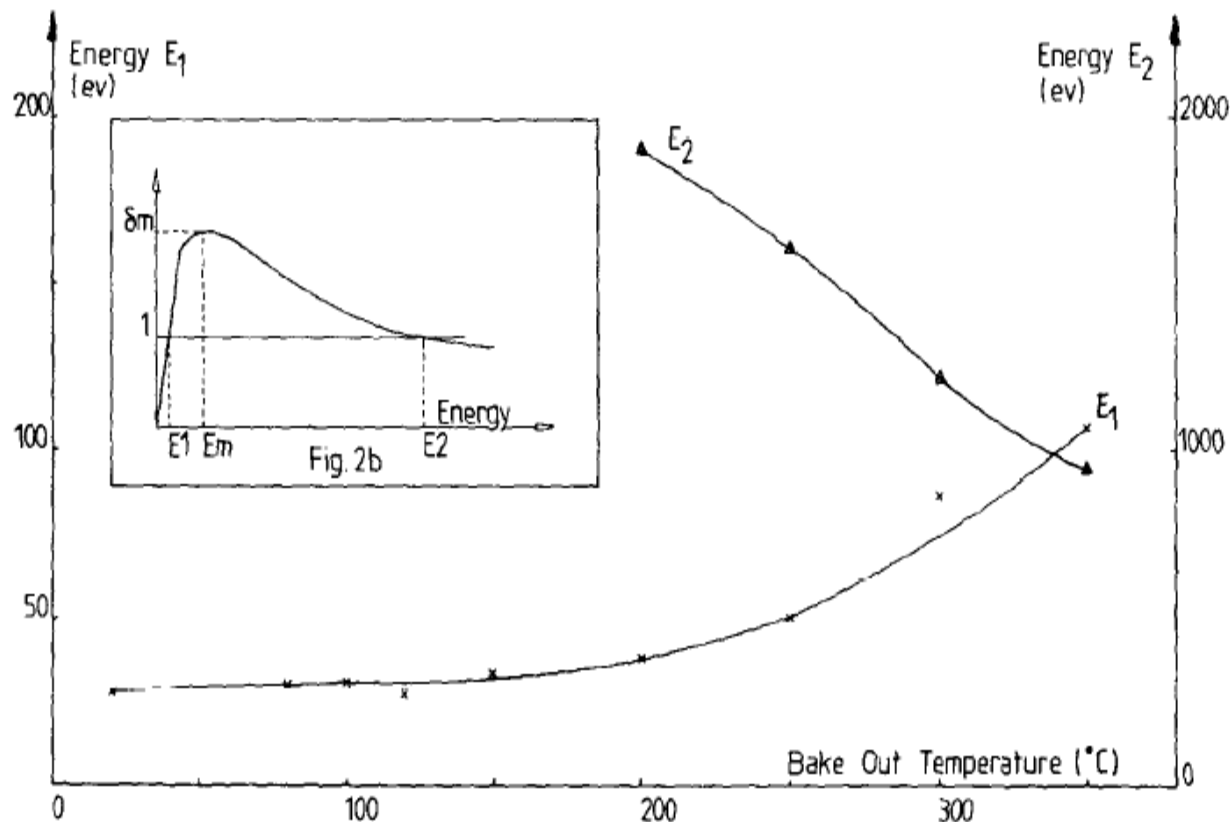
Condition	K_1	K_2
high SEY	~ 27 eV	$\gtrsim 2000$ eV
typical SEY	~ 40 eV	~ 1000 eV
low SEY	~ 150 eV	~ 750 eV

Secondary Emission in Niobium

INFLUENCE OF VARIOUS VACUUM SURFACE TREATMENTS ON THE SECONDARY ELECTRON YIELD OF NIOBIUM

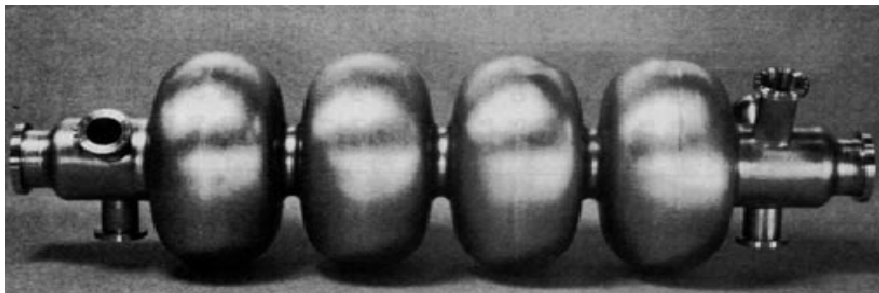
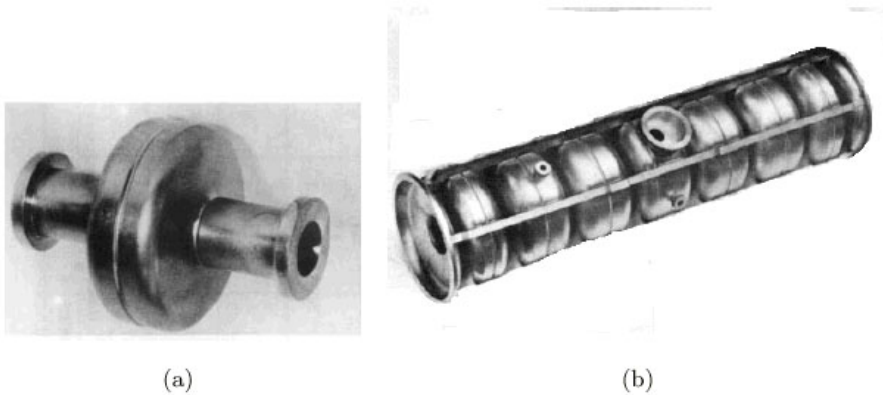
Roger CALDER, Georges DOMINICHINI and Noël HILLERET

LEP-VA, CERN, 1211 Geneva 23, Switzerland

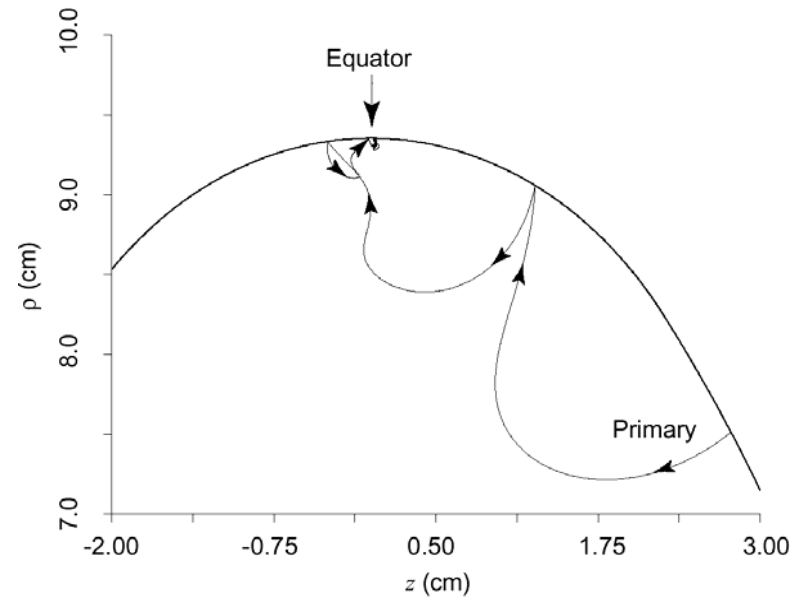


Multipacting

Multipacting was “eliminated” by rounding the shape of the pill-box cavity



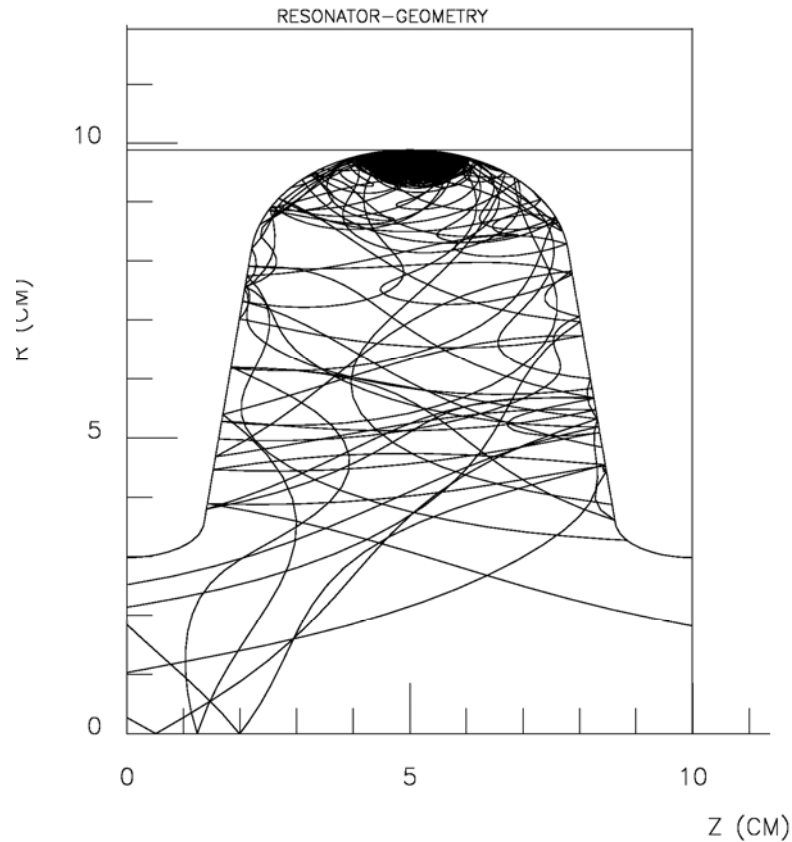
350-MHz LEP-II cavity (CERN)



Electrons drift to equator
Electric field at equator is 0
→MP electrons don't gain energy
→MP stops

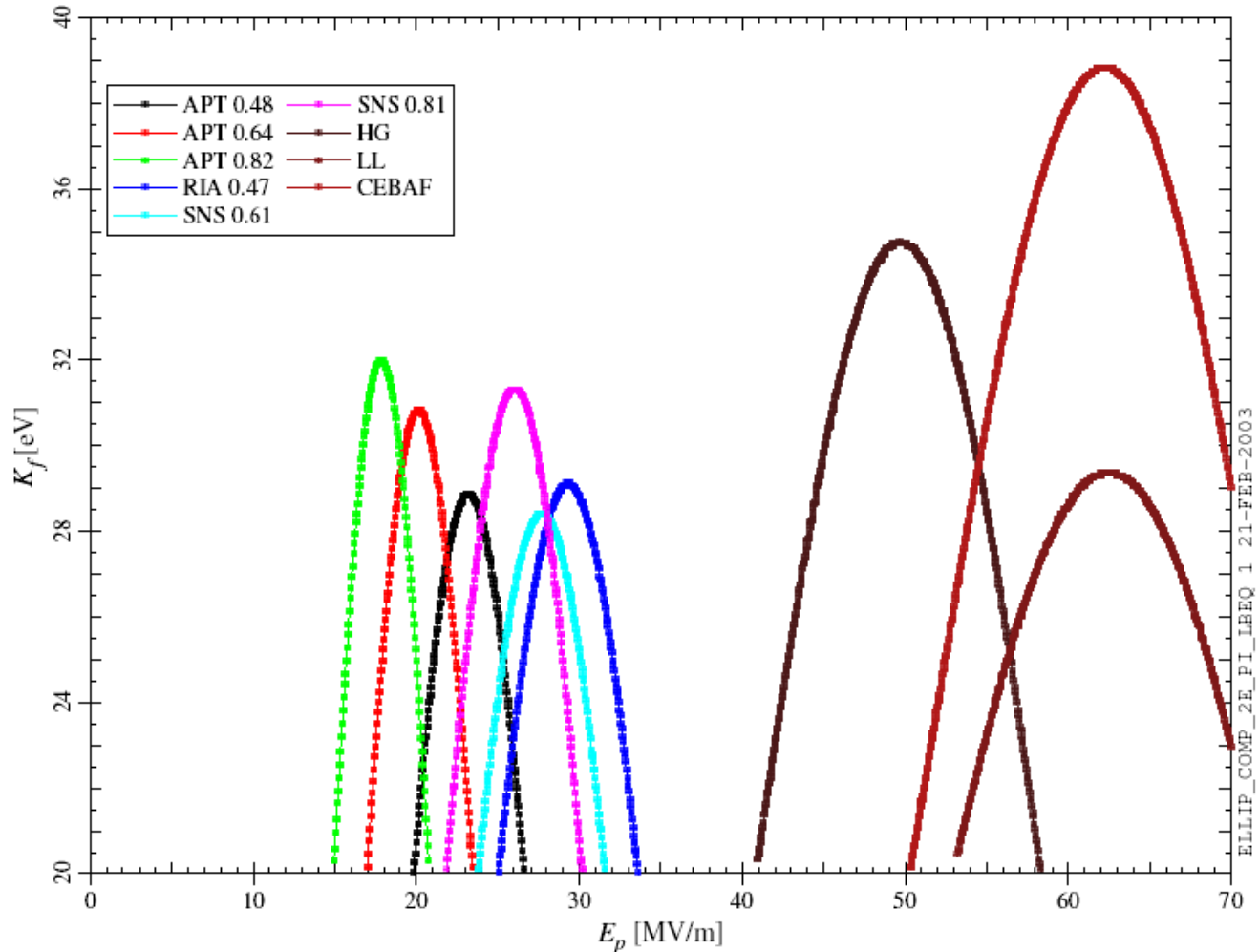
Multipacting Simulation

TRAJECTORIES #
EMAX= -14.260 MV/M BMAX= 224.389 GAUSS



Multipacting

SLANS + SMULTIP, $\omega\Delta t = \pi$
bnds 20 eV to 3 keV; $K_i = 2$ eV, $\alpha_i = 0$



Thermal Breakdown

Localized heating

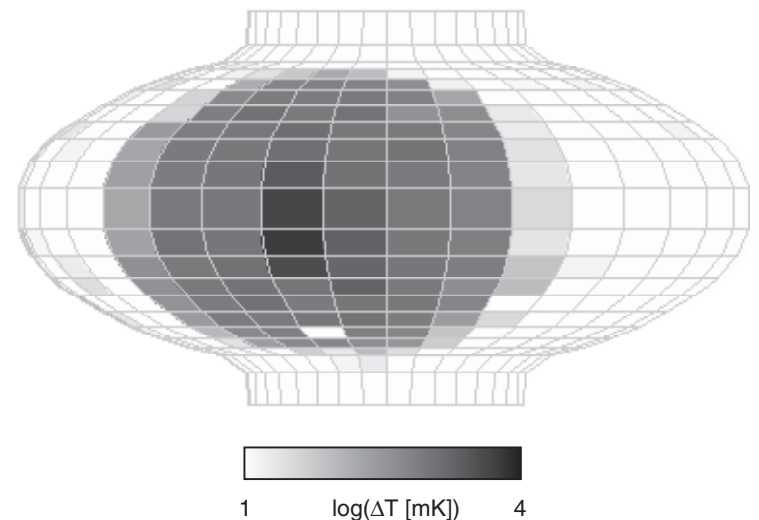
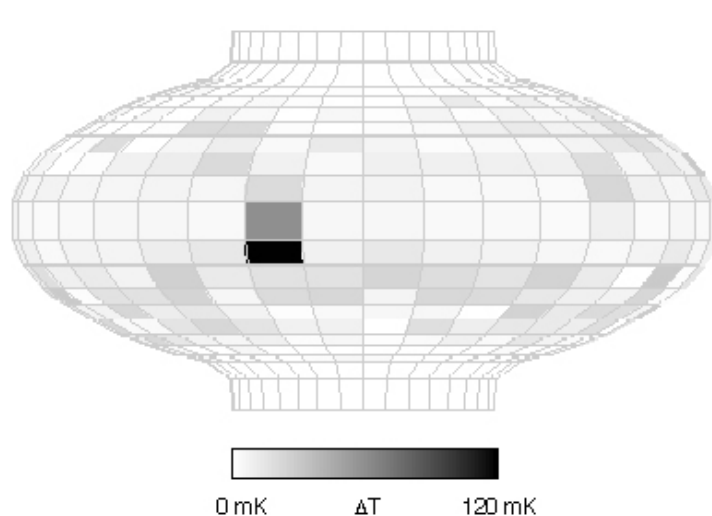
Hot area increases with field

At a certain field there is a thermal runaway, the field collapses

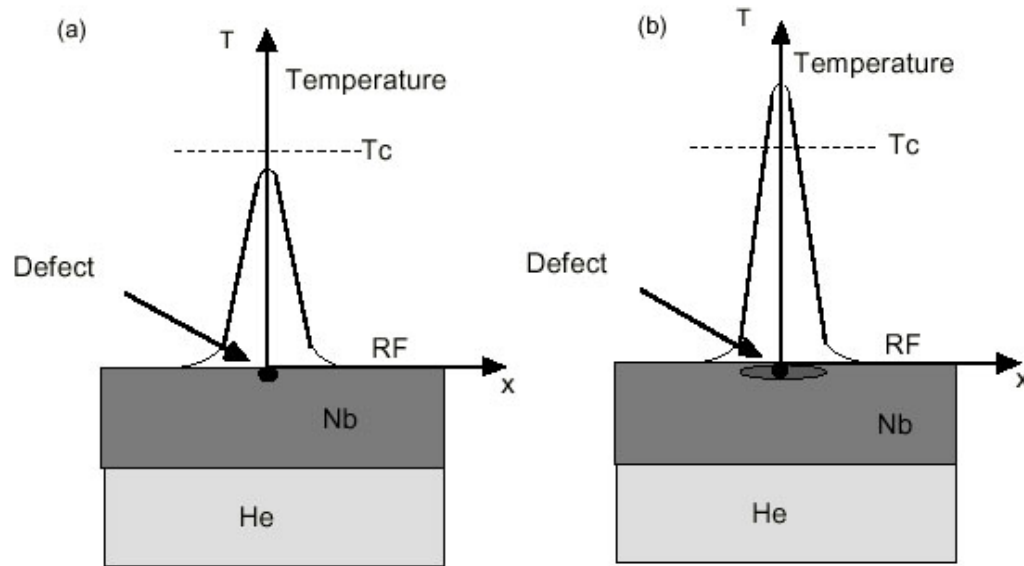
sometimes displays a oscillator behavior

sometimes settles at a lower value

sometimes displays a hysteretic behavior



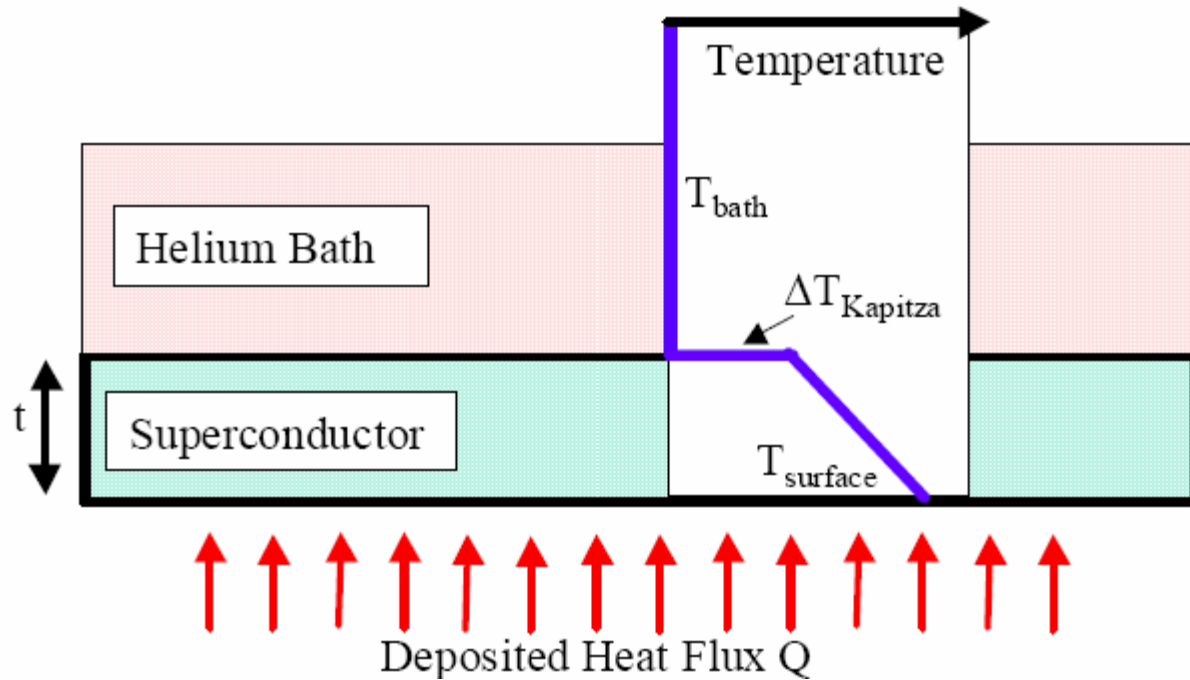
Thermal Breakdown



Thermal breakdown occurs when the heat generated at the hot spot is larger than that can be evacuated to the helium bath

Both the thermal conductivity and the surface resistance of Nb are highly temperature dependent between 2 and 9K

Thermal Breakdown



Residual Resistance Ratio

RRR is the ratio of the resistivity at 300K and 4.2K

$$RRR = \frac{\rho(300K)}{\rho(4.2K)}$$

RRR is related to the mean free path.

For Nb: $l(T = 4.2K) \approx 27 RRR \text{ (\AA)}$

RRR is related to the thermal conductivity

For Nb: $\lambda(T = 4.2K) \approx RRR / 4 \text{ (W. m}^{-1} \cdot \text{K}^{-1}\text{)}$

Residual Resistance Ratio

Table 6.1: Expected residual resistivity ratio contribution for niobium for 1 ppm wt of impurities^a

Element	RRR	Element	RRR
H	2640	Zr	102 000–239 000
N	4230	Hf	200 000
C	4380	W	262 000–721 000
O	5580	Mo	717 000
Ti	53 700	Ta	1 140 000

^aThe ideal RRR due to phonon scattering is 35 000. To obtain the RRR one must add the resistance contributions for each impurity element in parallel to the resistance contribution from phonons.

Thermal Conductivity of Nb

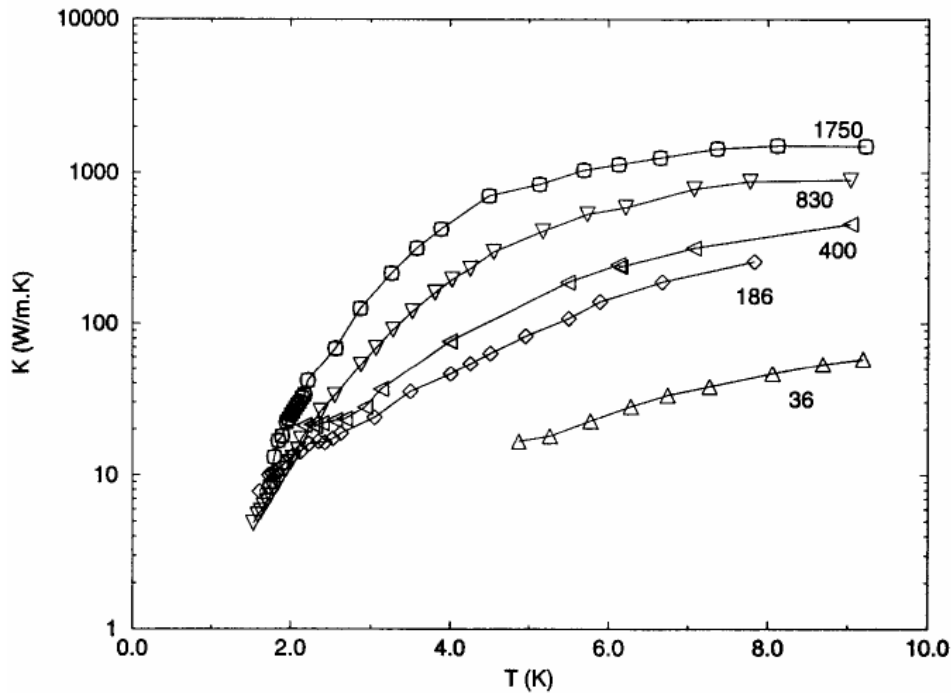
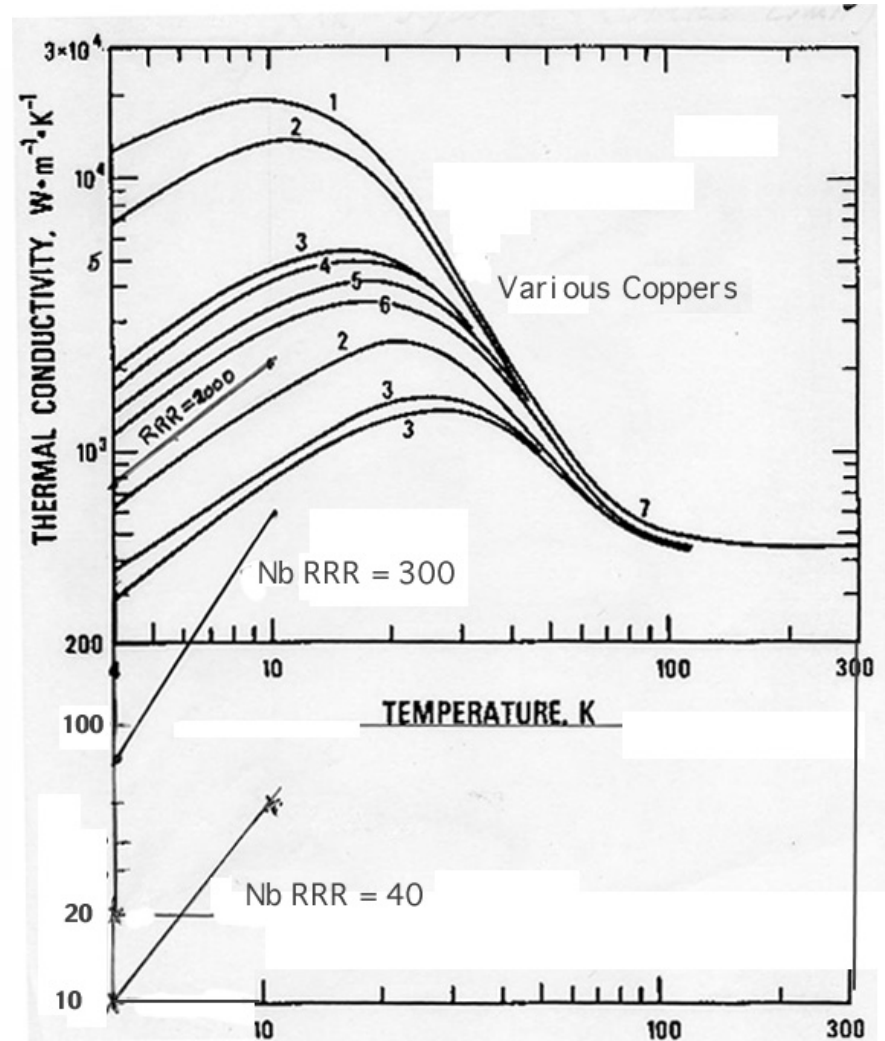
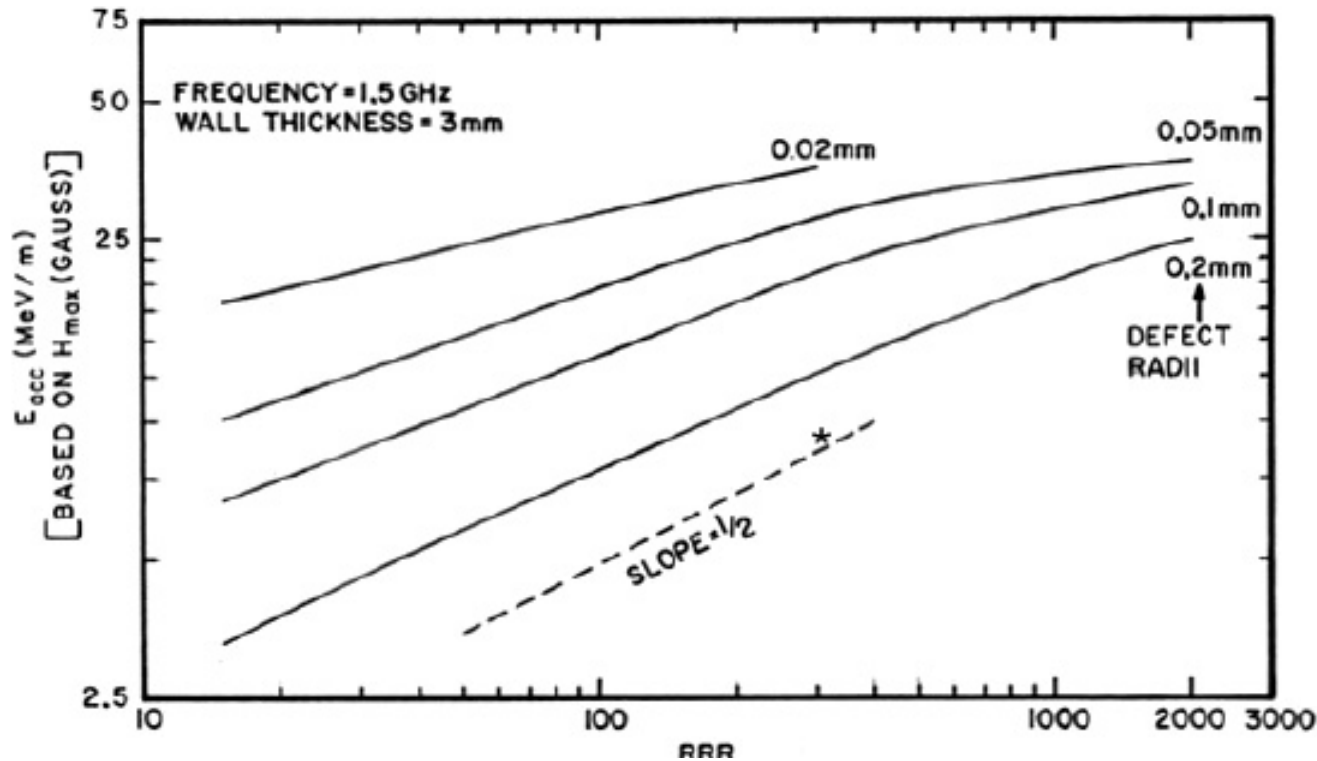


Fig. 3 The thermal conductivity of niobium as a function of temperature, for various RRR values.



Thermal Breakdown

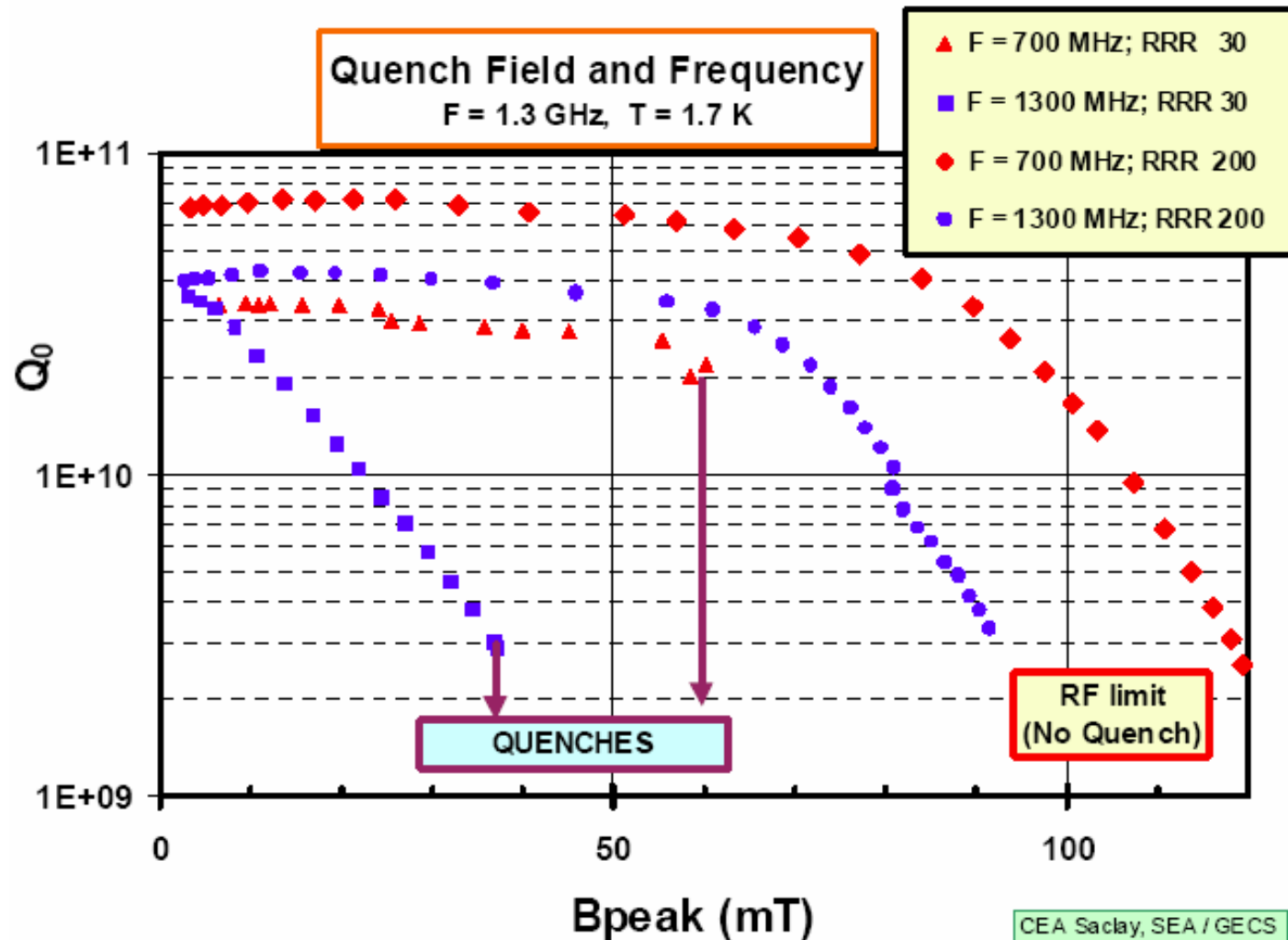


Breakdown field given by (very approximately):

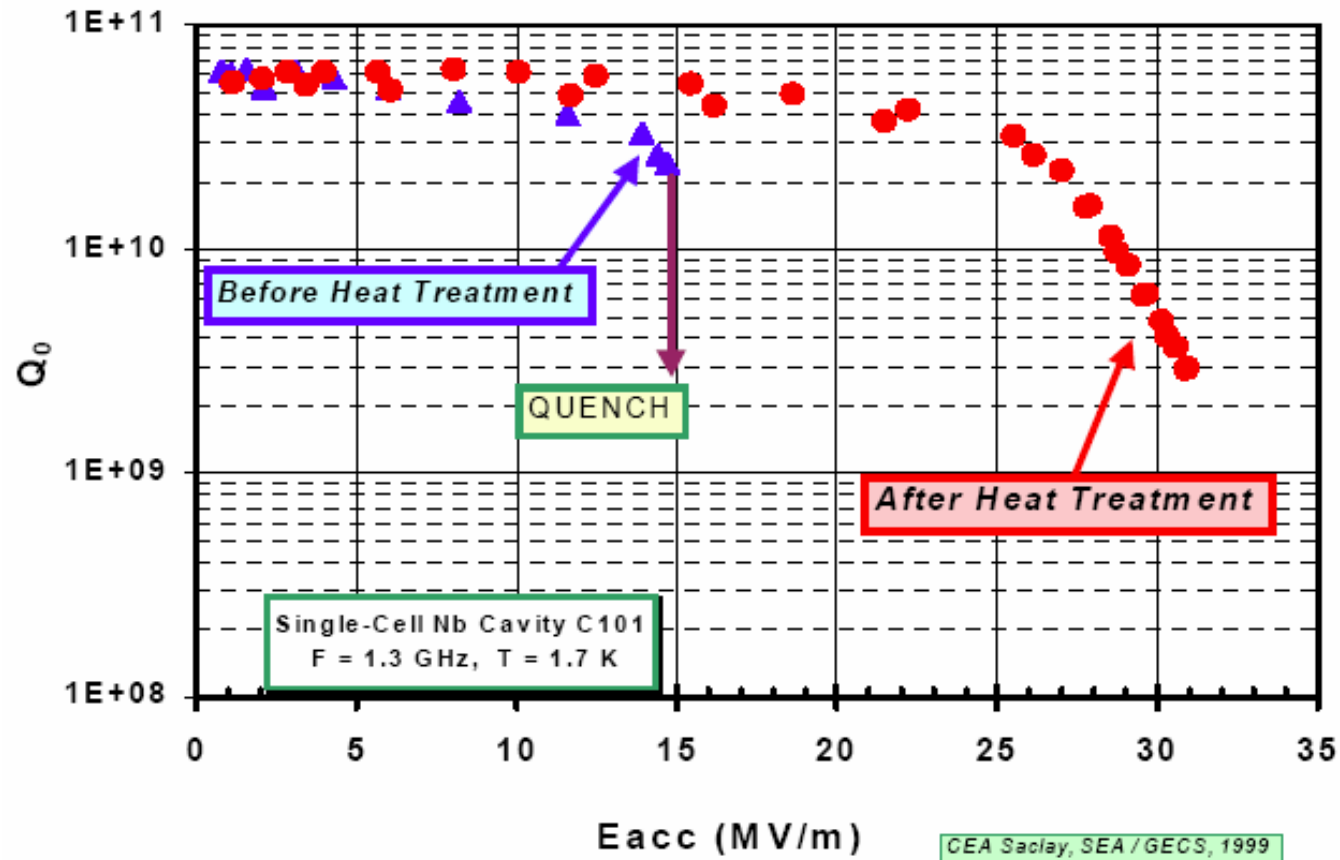
$$H_{tb} = \sqrt{\frac{4\kappa_T(T_c - T_b)}{r_d R_d}}$$

- κ_T : Thermal conductivity of Nb
- R_d : Defect surface resistance
- T_c : Critical temperature of Nb
- T_b : Bath temperature

Thermal Breakdown

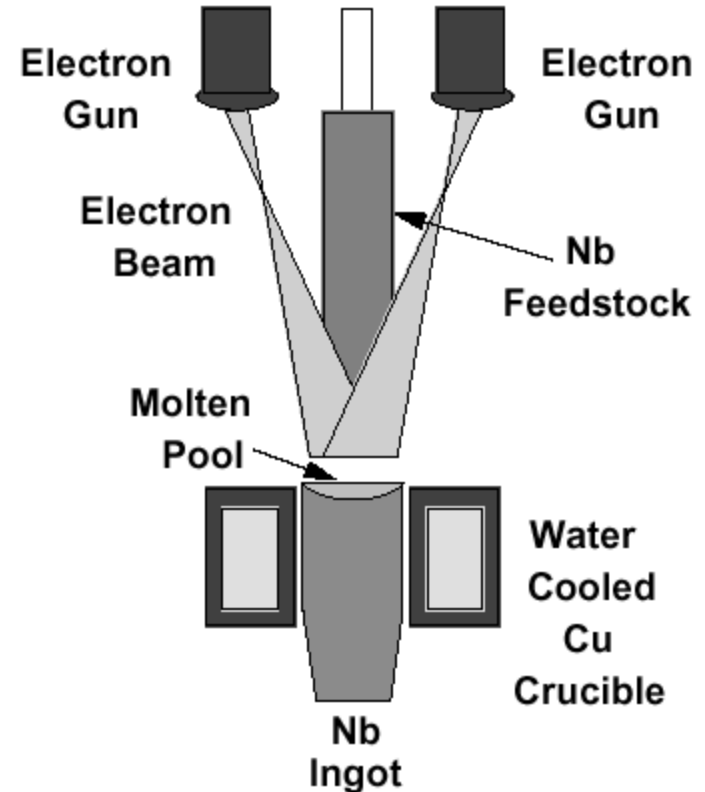


Thermal Breakdown



Niobium Purification

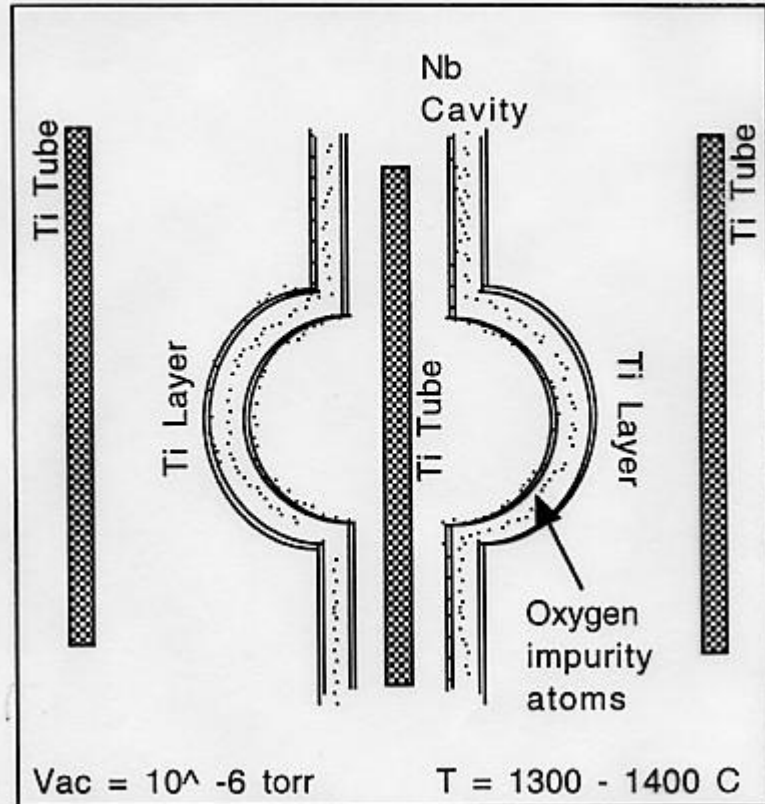
- Can produce high Nb purity by e-beam melting in a vacuum furnace
- Currently industry produces RRR 300-400 Nb.
- Reactor grade Nb is RRR = 40
- Theoretical limit is RRR = 32,000.



RRR: Residual resistance ratio = resistivity at room temperature divided by the resistivity at 4.2 K (in the normal conducting state!). T_c scales linearly with RRR.

Niobium Purification

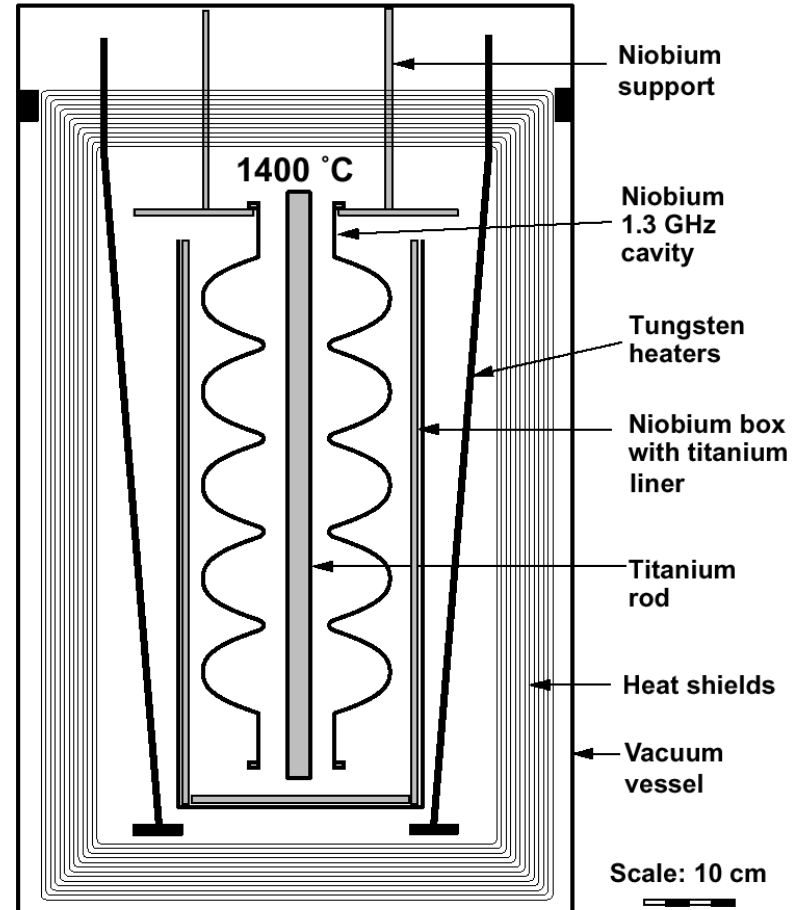
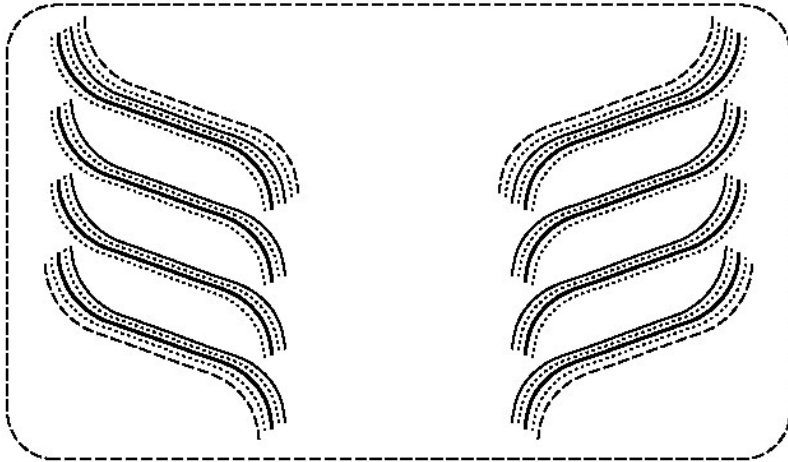
Post Purification



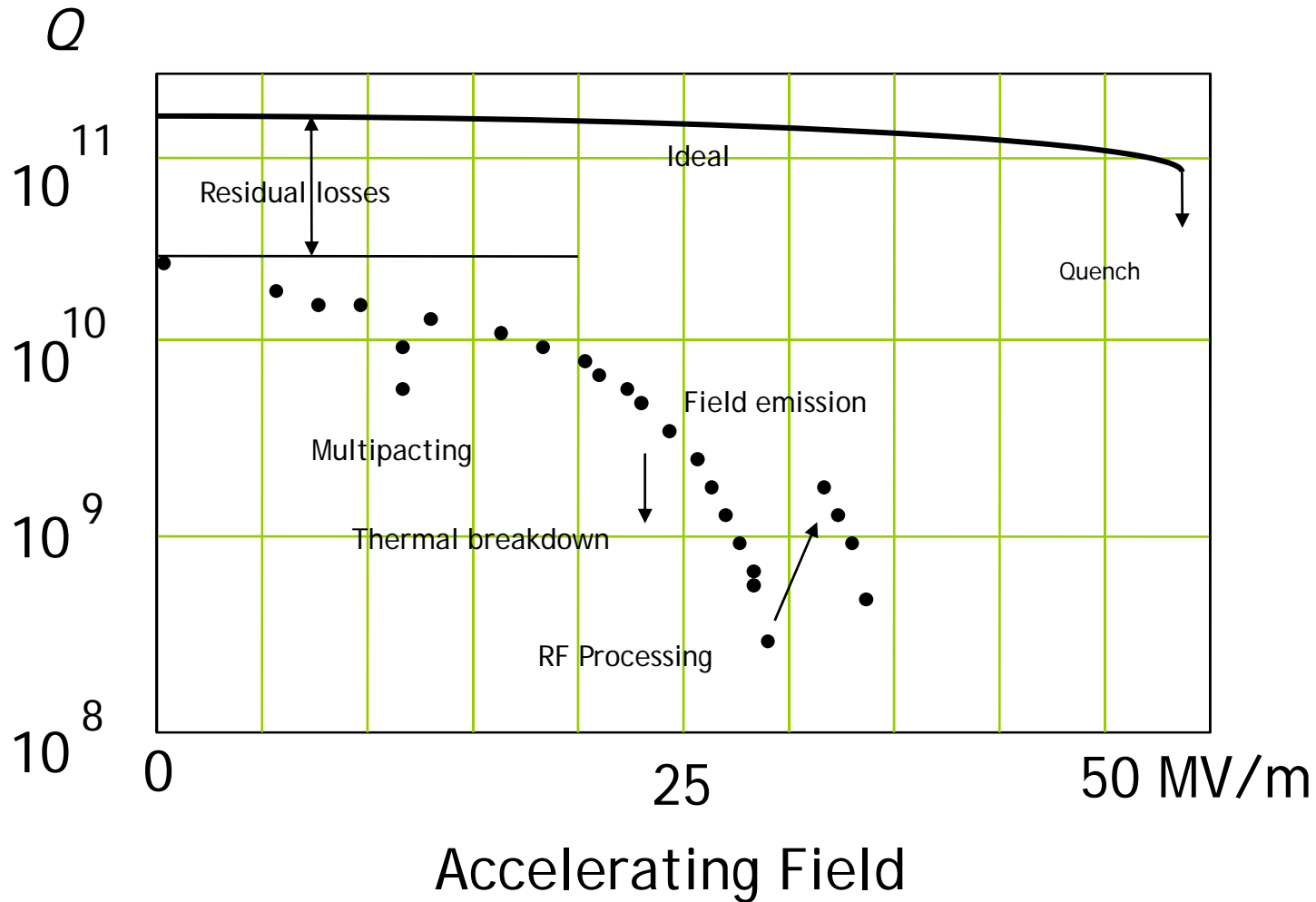
- After cavity or half-cell is produced
 - Heat in vacuum furnace to ~ 1400 C
 - Evaporate Ti on cavity surface
 - Use titanium as getter to capture impurities
 - Later etch away the titanium
 - Doubles the purity (RRR ~ 600 if originally RRR = 300)

Post Purifying Niobium

- Nb cavity half-cell
- ⋯ Perforated Nb foil
- Y foil
- - - Nb foil



The Real World



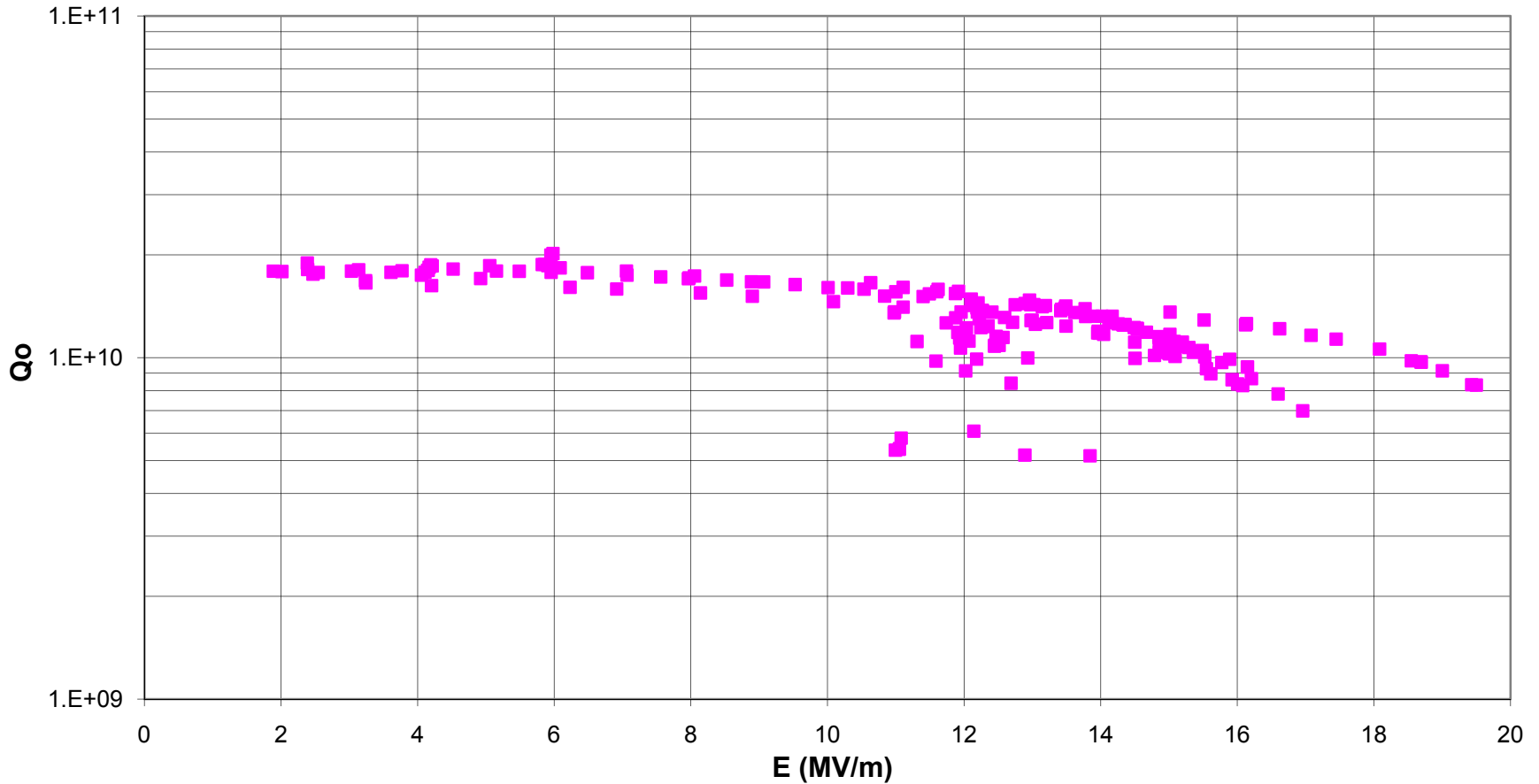
Field Emission

Characterized by an exponential drop of the Q

Associated with production of x-rays and emission of dark current

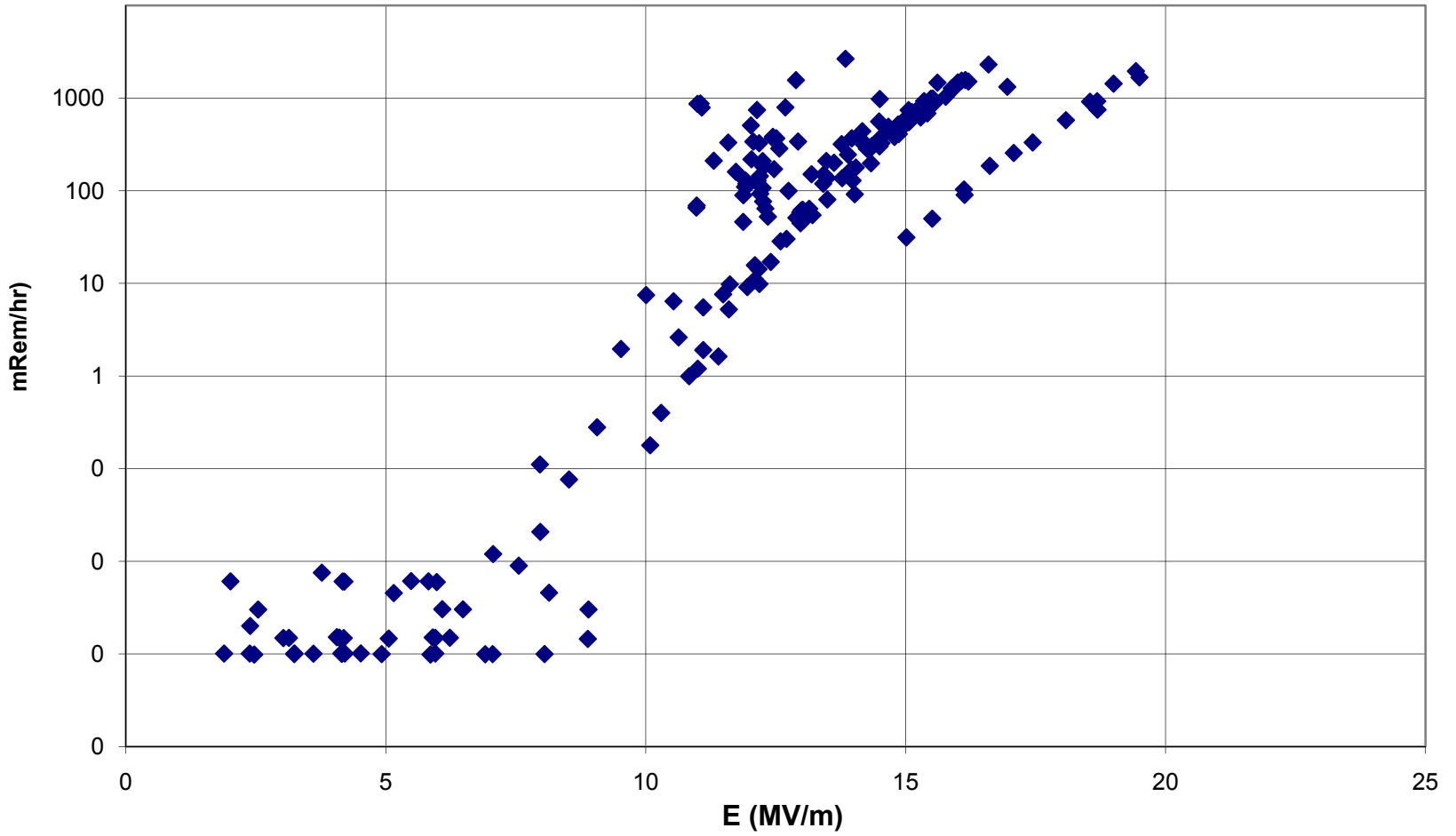
Field Emission

SNS HB54 Qo versus Eacc
Multipacting limited at 16MV/m 5/16/08 cg



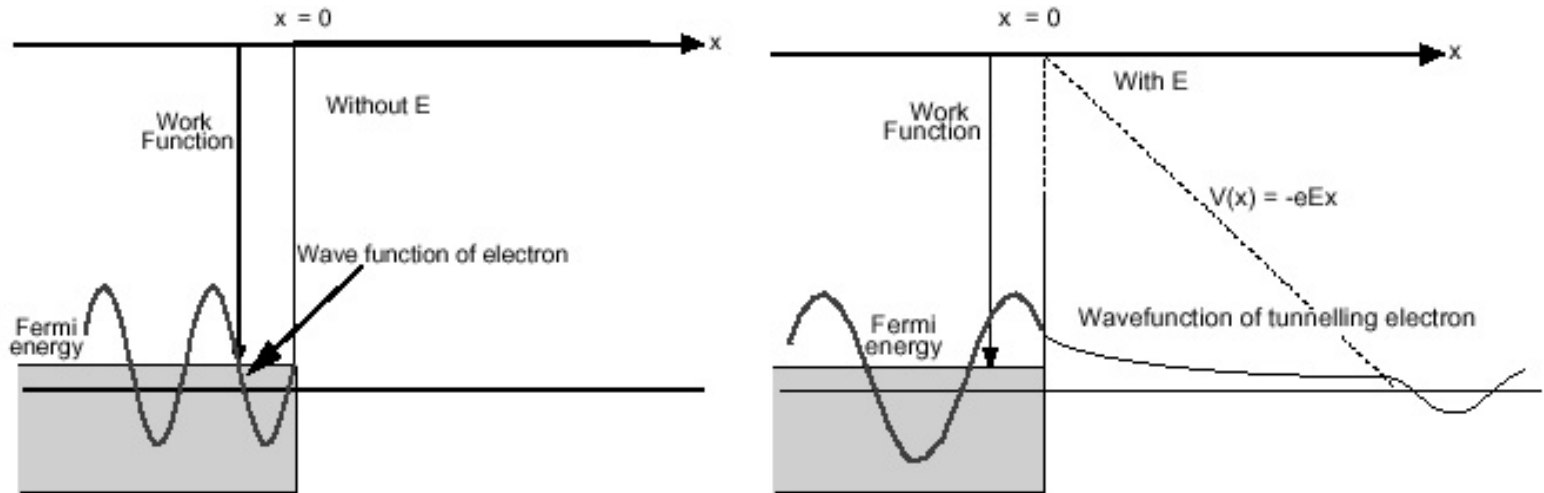
Field Emission

SNS HTB 54 Radiation at top plate versus Eacc 5/16/08 cg



DC Field Emission from Ideal Surface

Fowler-Nordheim model



$$J = \frac{1.54 \times 10^{-6} E^2}{\Phi} \exp\left(-\frac{6.83 \times 10^9 \Phi^{3/2}}{E}\right)$$

J : Current density (A/m^2)

E : Electric field (MV/m)

Φ : Work function (eV)

Field Emission in rf Cavities

$$J = k \frac{1.54 \times 10^{-6} (\beta E)^{5/2}}{\Phi} \exp\left(-\frac{6.83 \times 10^9 \Phi^{3/2}}{\beta E}\right)$$

β : Enhancement factor (10s to 100s)

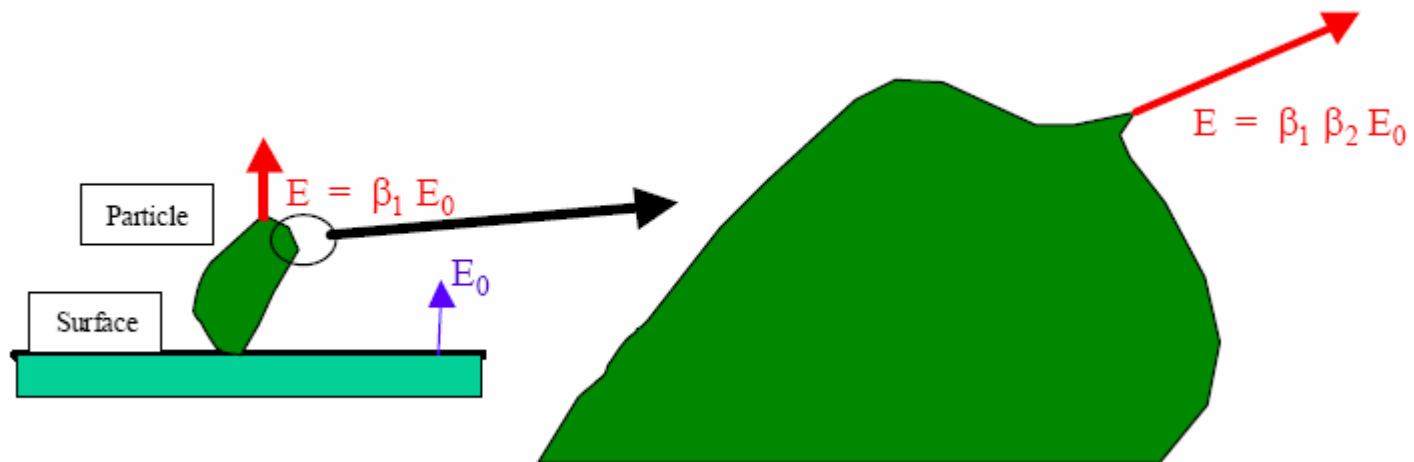
k : Effective emitting surface

Geometrical Origin of Field Enhancement

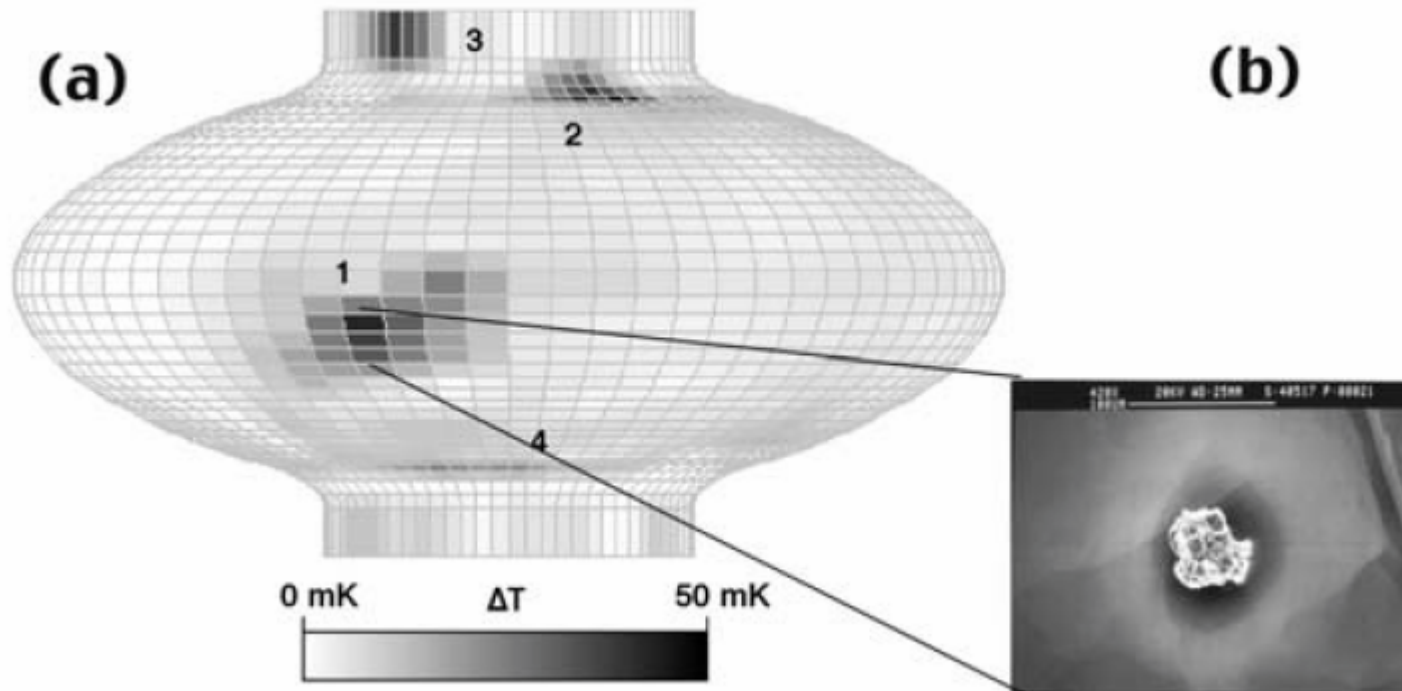
Smooth particles show little field emission

Simple protrusions are not sufficient to explain the measured enhancement factors

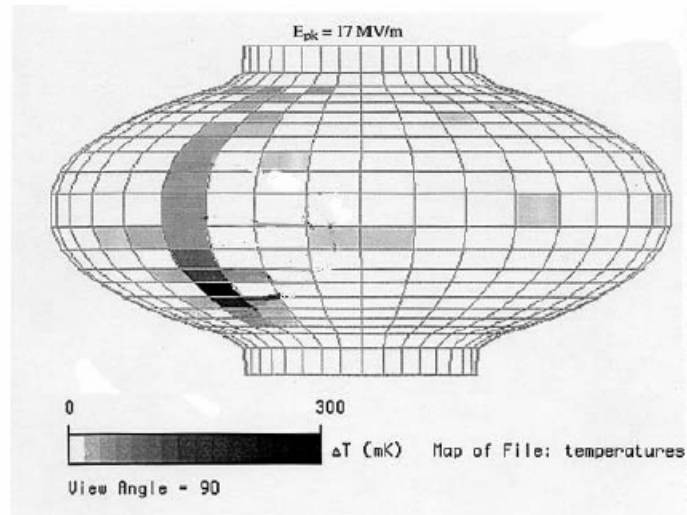
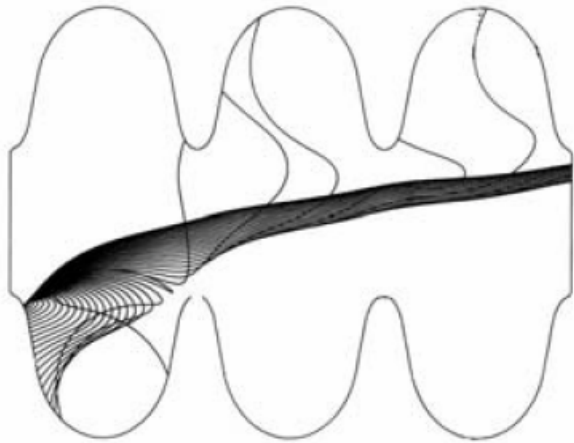
Possible explanation: tip on tip (compounded enhancement)



Localized Defects



Field Emission

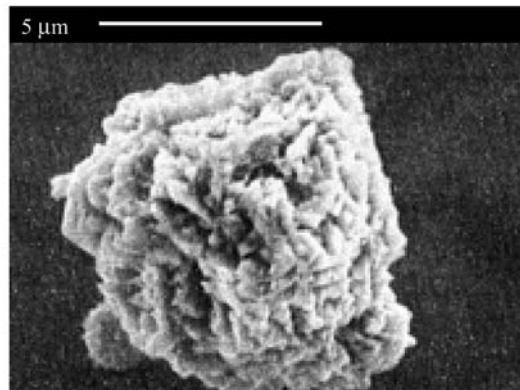
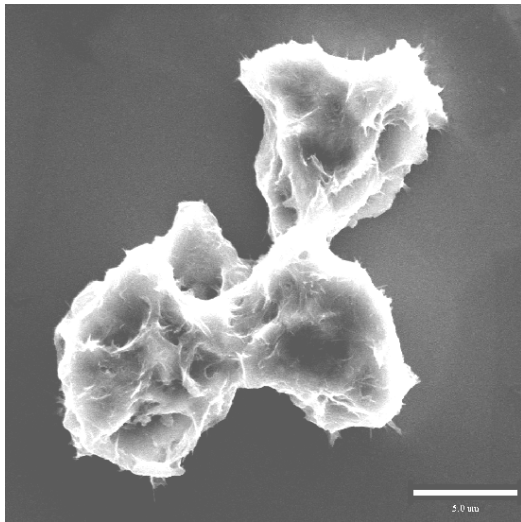


Example of Field Emitters

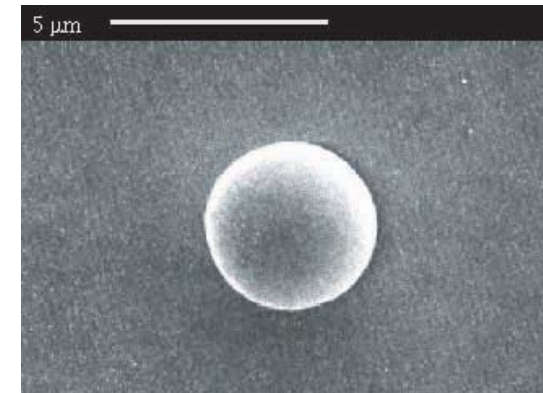


Fig. 11 Example of a scratch and a particle on a niobium surface.

V



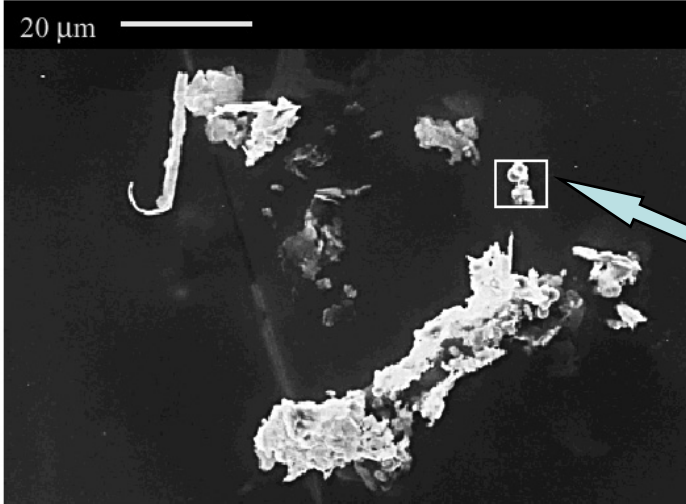
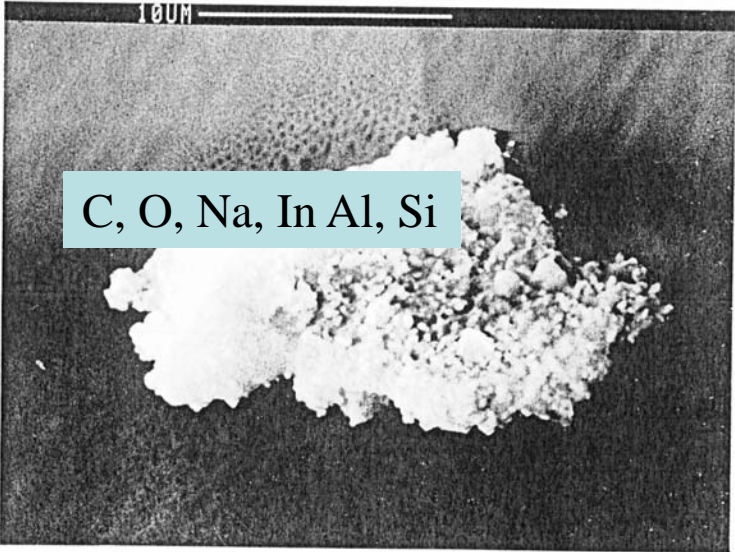
Ni



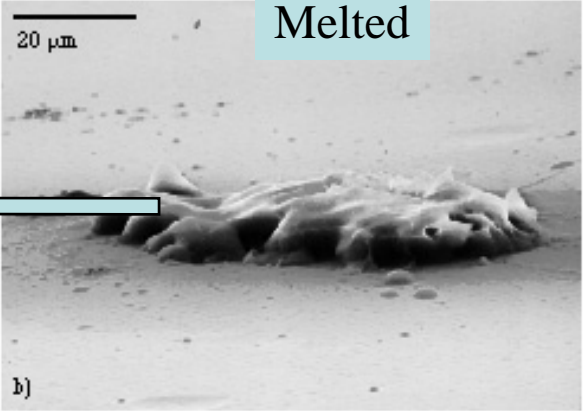
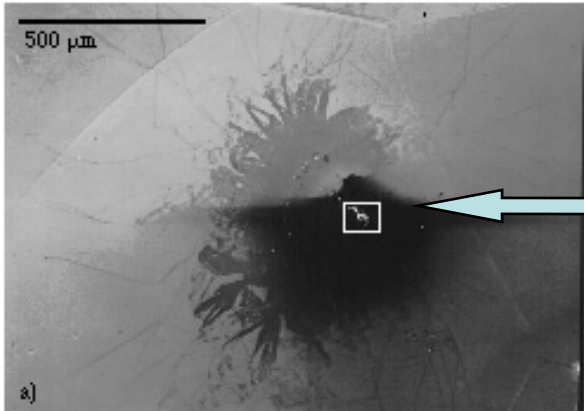
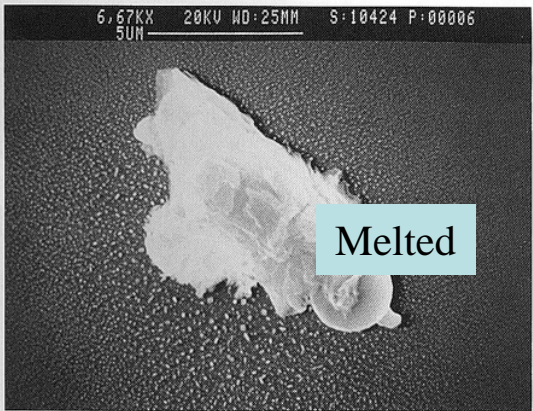
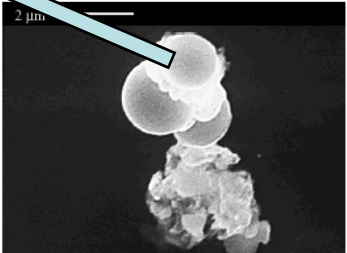
Ni

Example of Field Emitters

Stainless steel

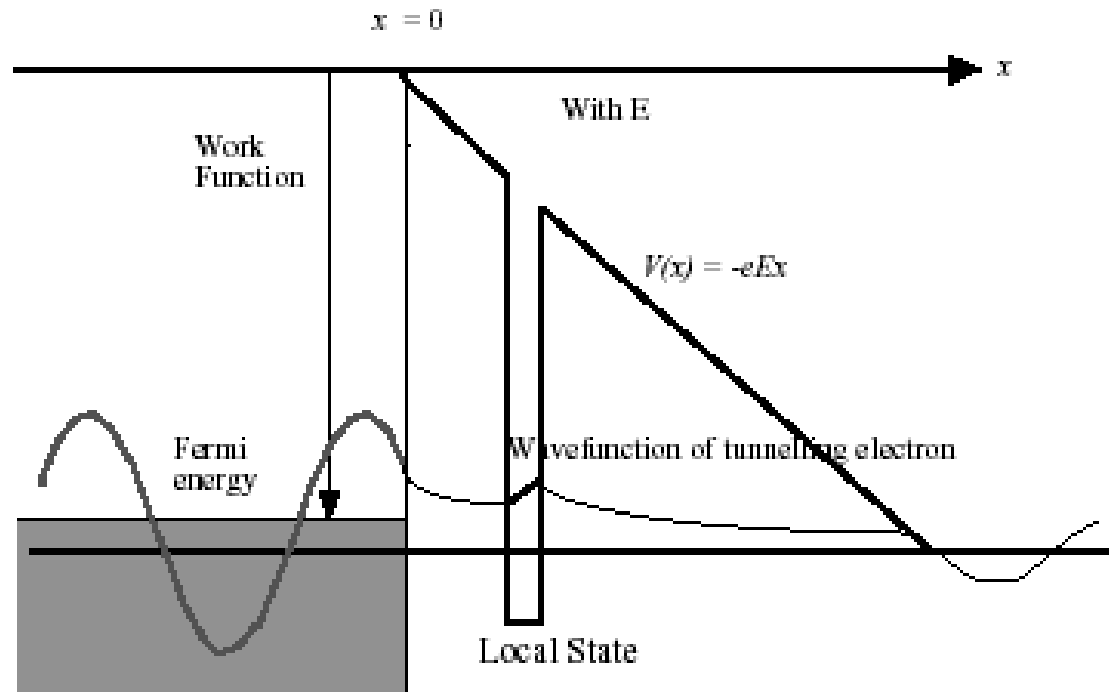


Melted



Enhancement by Adsorbates

Adsorbed atoms on the surface can enhance the tunneling of electrons from the metal and increase field emission



Field Emission

Surface electric field is not a fundamental limitation

Surface fields above 100 MV/m over many cm² have been maintained cw in superconducting cavities (>200 MV/m for ms)

However field emission is still the main limitation

The main cause of field emission is particulate contamination

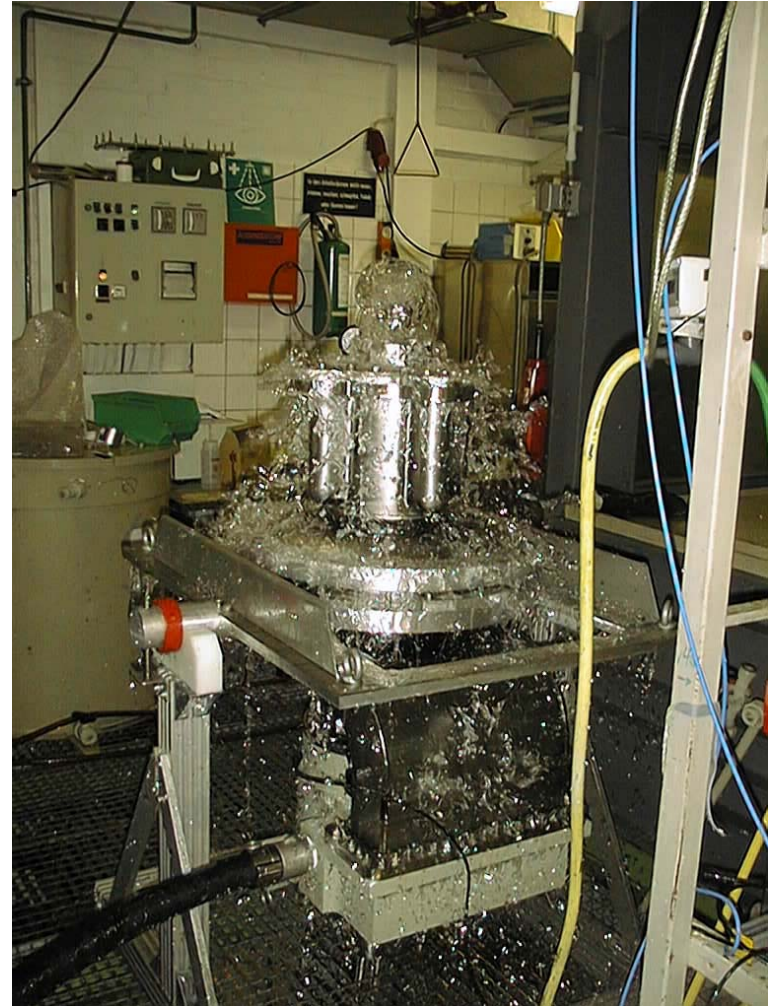
Contamination Prevention

- **Sources of contamination**
 - Processing Chemicals (filtered!)
 - High Purity Water (>18 MΩcm, <0.02 μm filter)
 - Clean Room environment (entrance, class 10)
 - Particulates on equipment, tooling, hardware, clothing, gloves..
- **Contamination control**
 - Stringent control of processes and procedures
 - In-line monitoring of particulate levels in air and liquids
 - Scheduled maintenance
 - “Blow-off” with filtered N₂, monitored by particle counter
 - Use of appropriate hardware (e.g. bolts..)
 - Clever designs (e.g.gaskets, clamp rings, fixtures...)
 - Consistent use of “best practices” through whole assembly process

Contamination Prevention

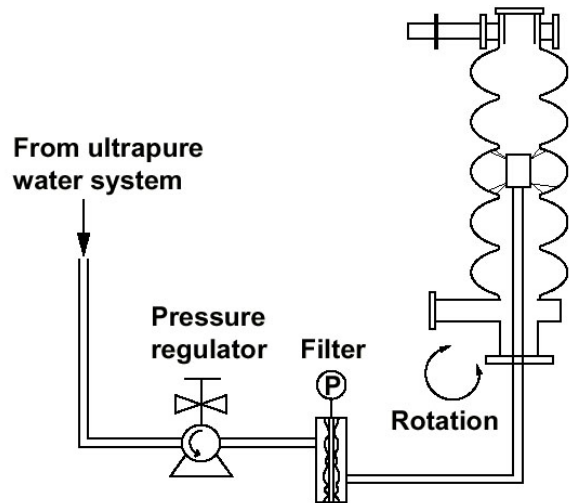
Continuous-flow rinse

Ultrapure water (18 M Ω -cm)
must be used for all treatments



High pressure rinsing (HPR)

- Rinsing of cavities with up to 1000 psi (100 bar) water jets removes many particles.



High Pressure Rinse Systems



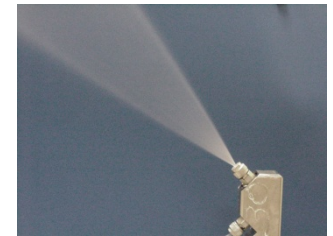
DESY-System



Jlab HPR Cabinet



KEK-System



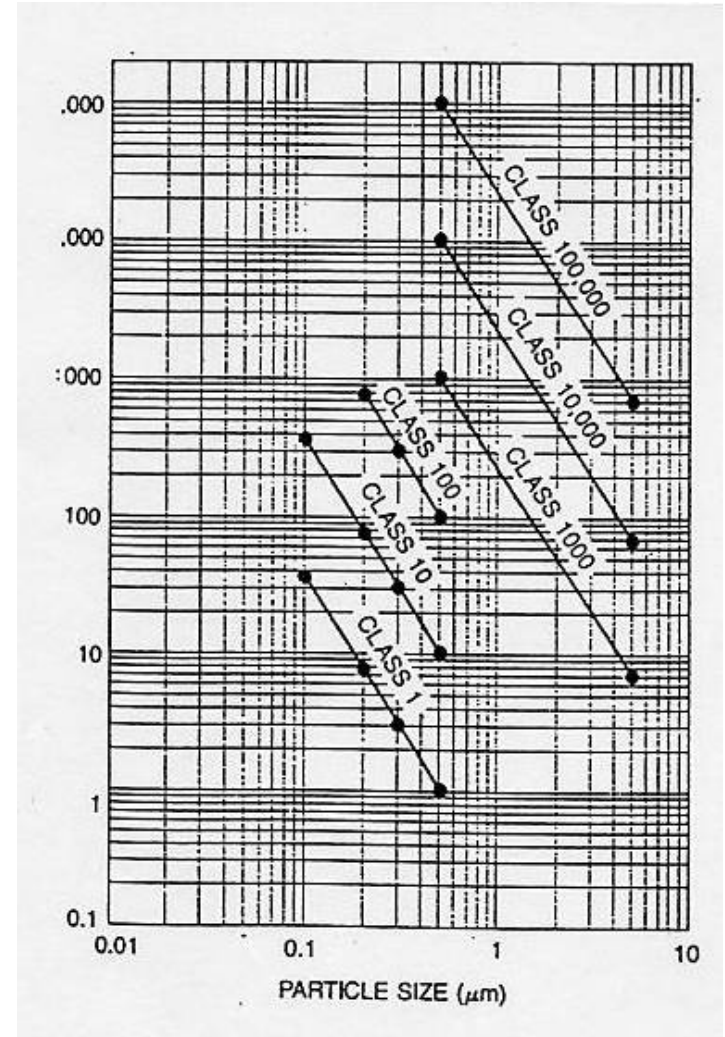
Clean Rooms

All cavities and vacuum components are assembled in a clean rooms (class 100 or better, <100 particle per ft^3 $>0.5\mu\text{m}$)

Components and tooling must be designed to be clean room compatible



TESLA cavity



Clean Rooms



Post Processing Contamination

Contamination can occur during string and cryomodule assembly

Accelerator beam lines are not clean

Particulate can migrate from beam line to cavities

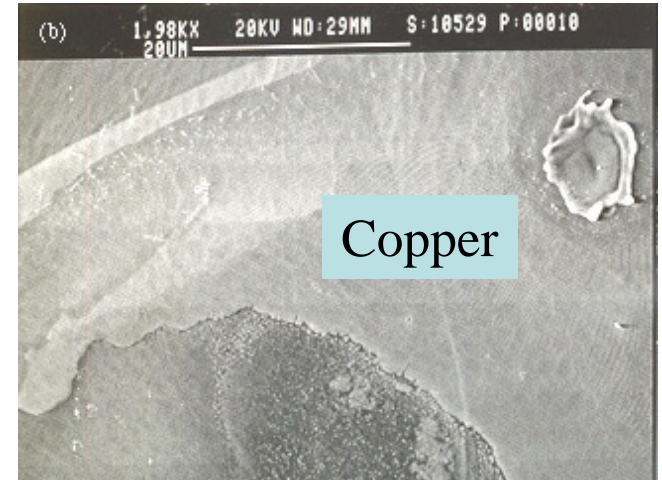
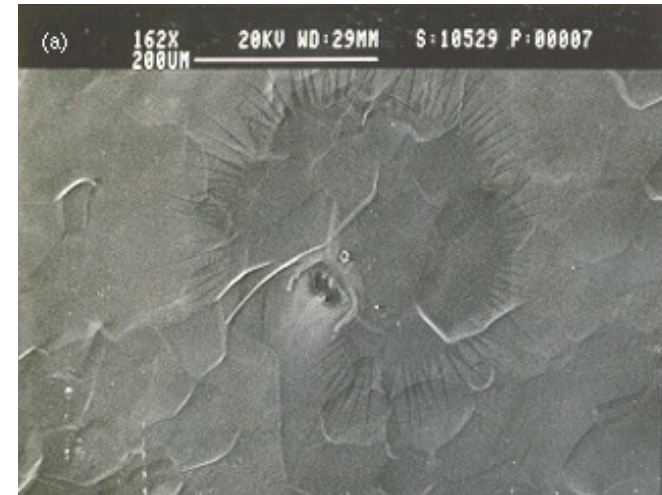
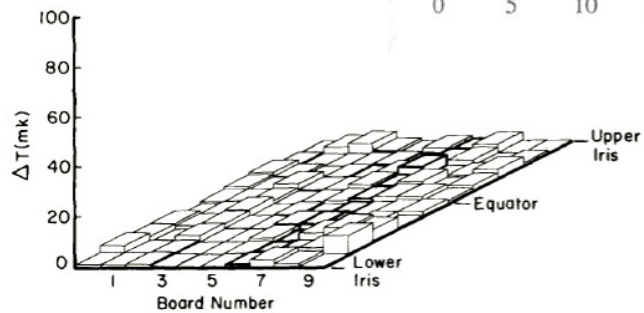
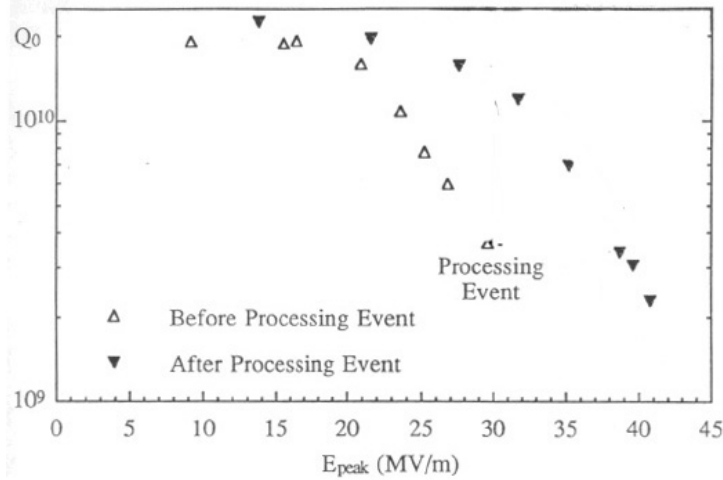
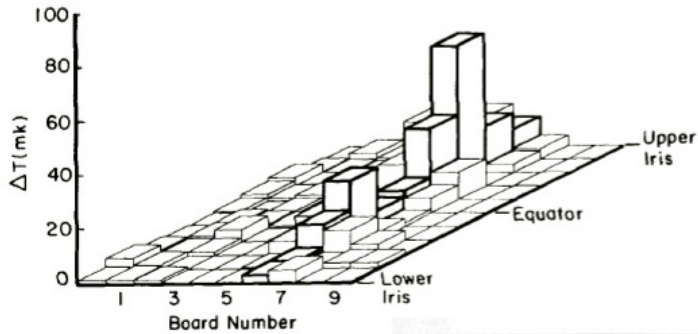
Vacuum accidents happen

Field emission can occur or increase during operation

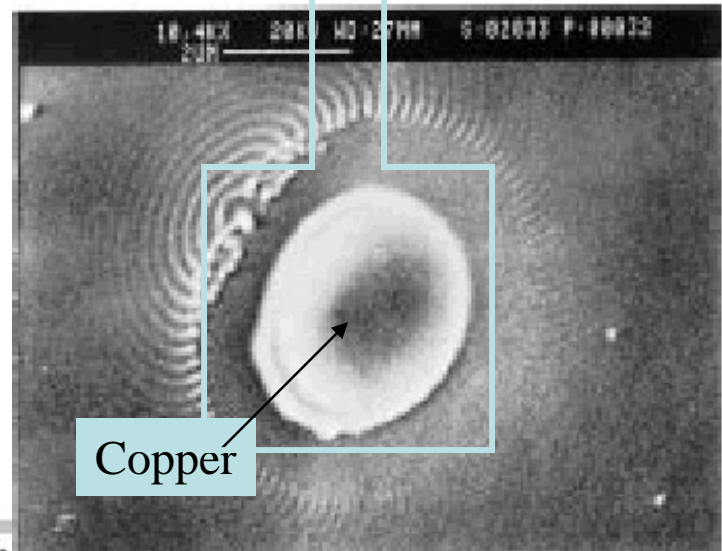
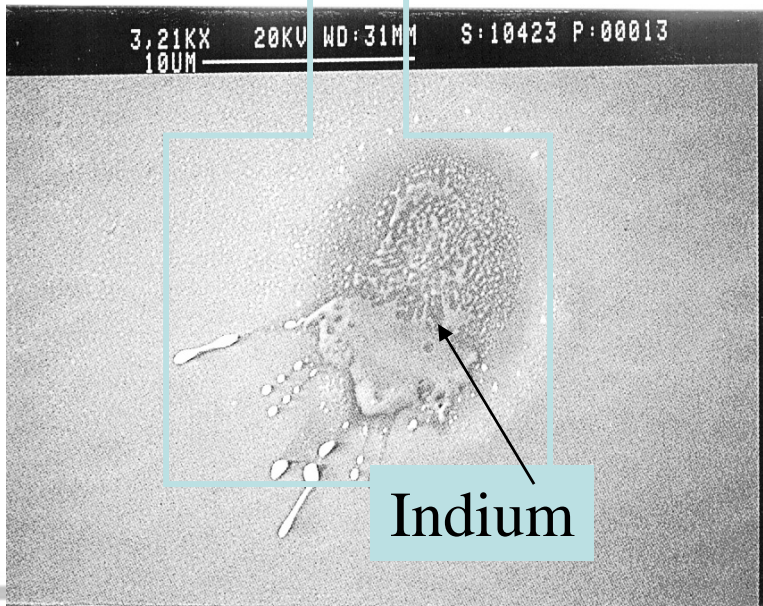
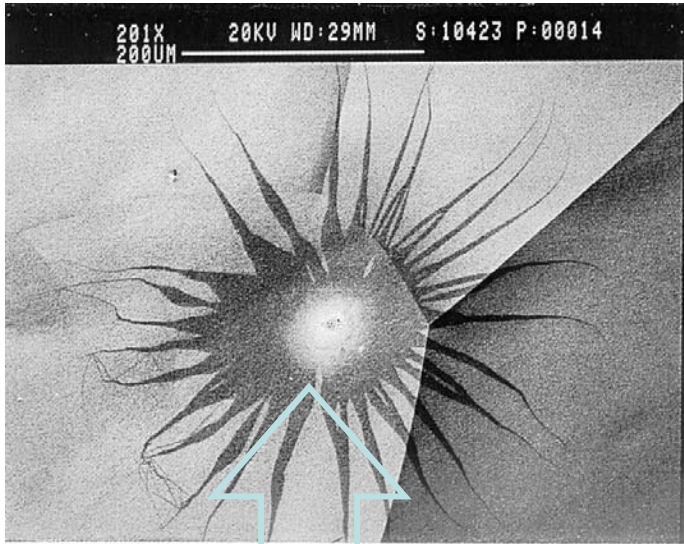
High power processing

Helium Processing

High Power Processing



High Power Processing



Helium Processing

Helium gas is introduced in the cavity at a pressure just below breakdown ($\sim 10^{-5}$ torr)

Cavity is operating at the highest field possible (in heavy field emission regime)

Duty cycle is adjusted to remain thermally stable

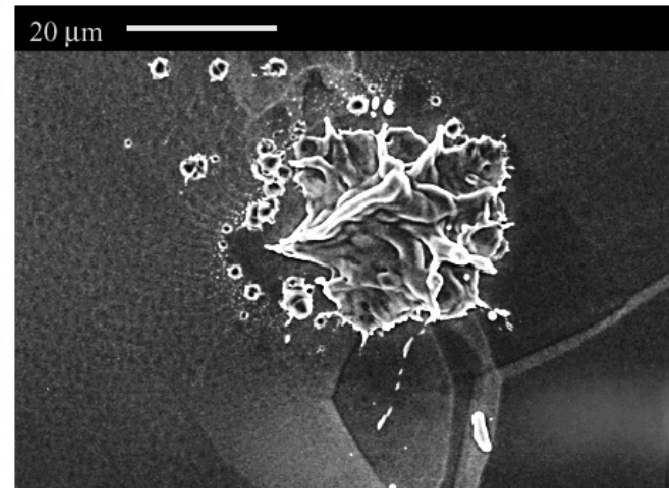
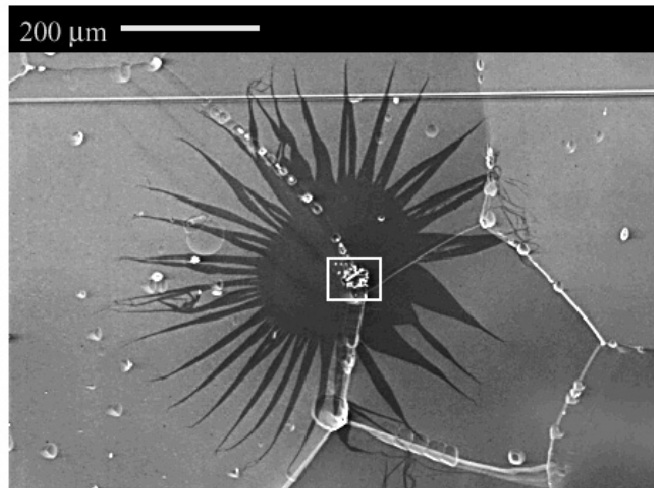
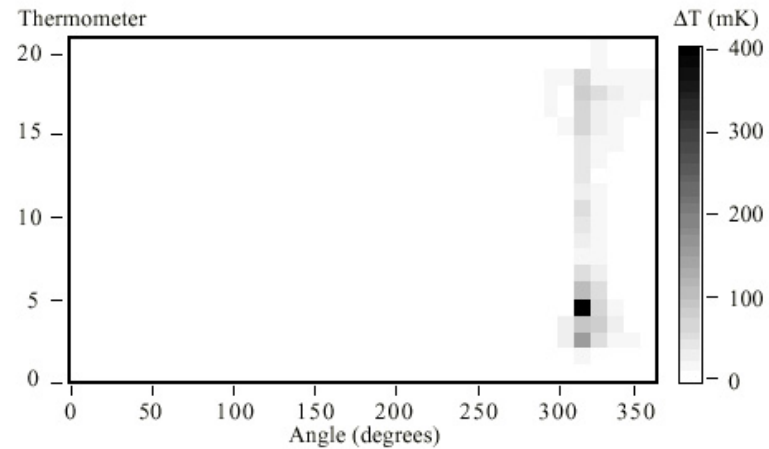
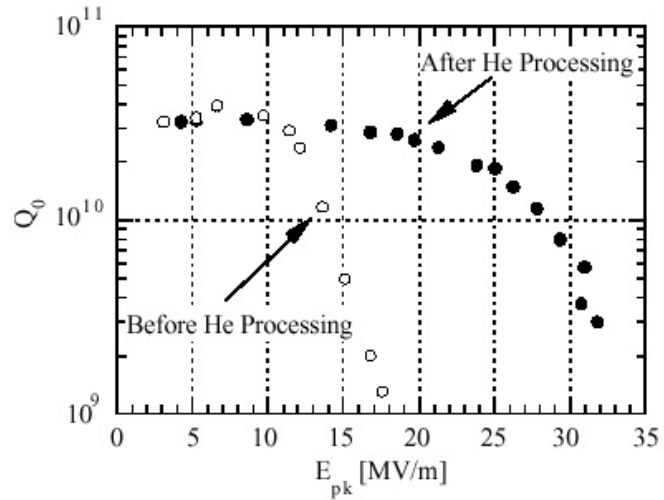
Field emitted electrons ionized helium gas

Helium ions stream back to emitting site

- Cleans surface contamination

- Sputters sharp protrusions

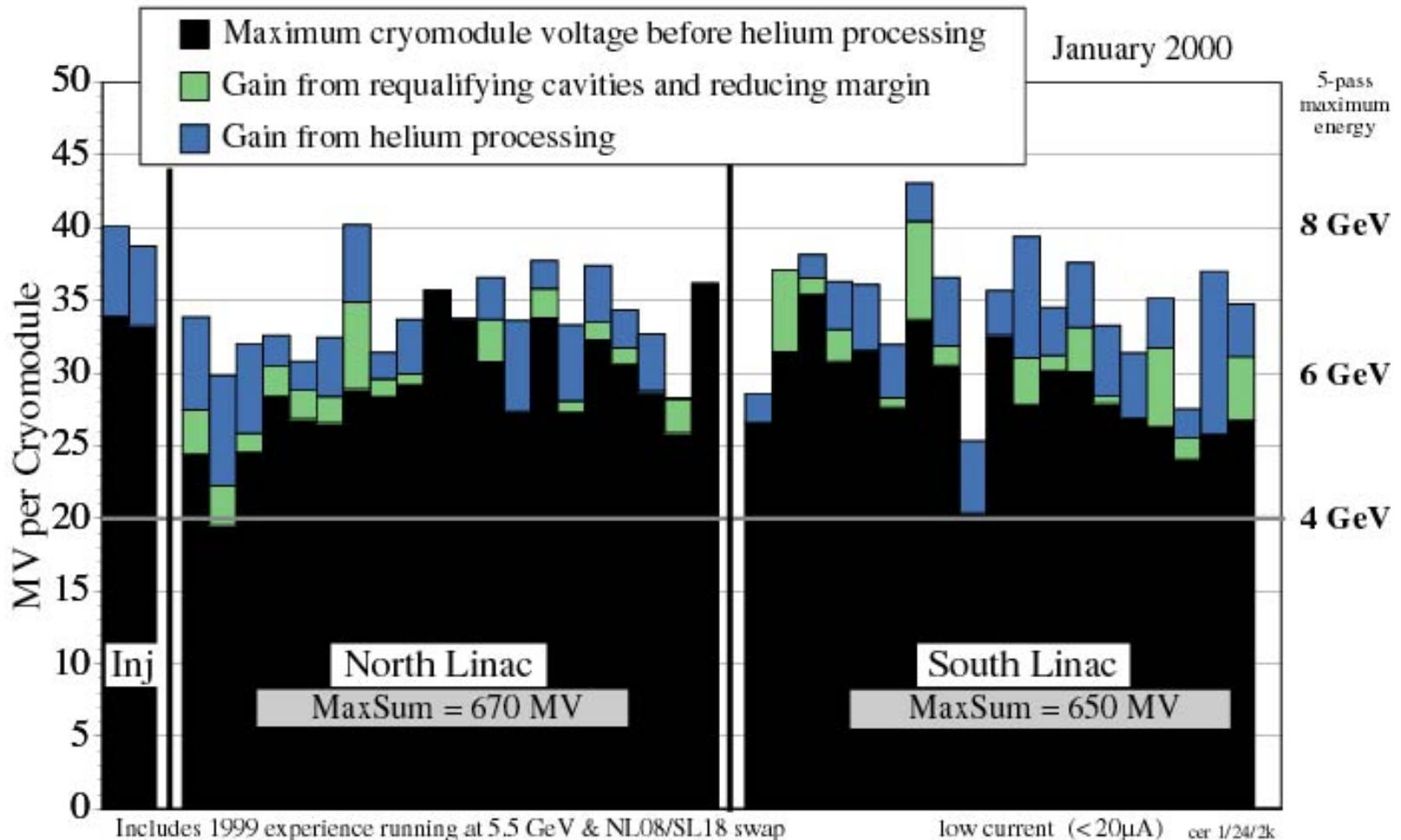
Helium Processing



Helium Processing in CEBAF

Maximum SRF Cavity Voltage per Cryomodule in CEBAF

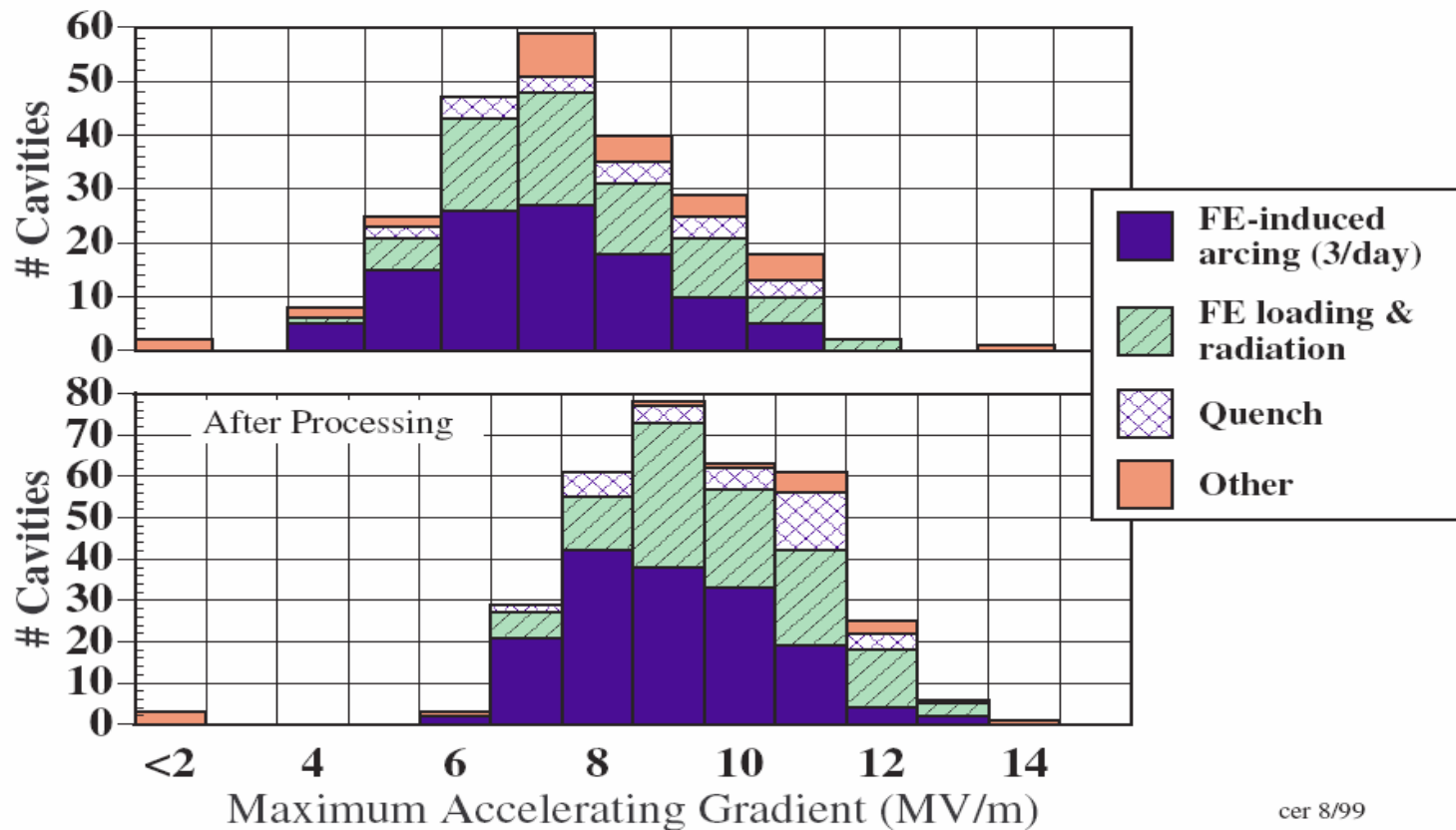
(Eight 0.5 meter, 1497 MHz srf cavities per cryomodule)



Helium Processing in CEBAF

Improvement of Cavity Performance with Helium Processing

Distribution of Maximum Gradients by Type of Limitation



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Helium Processing in CEBAF

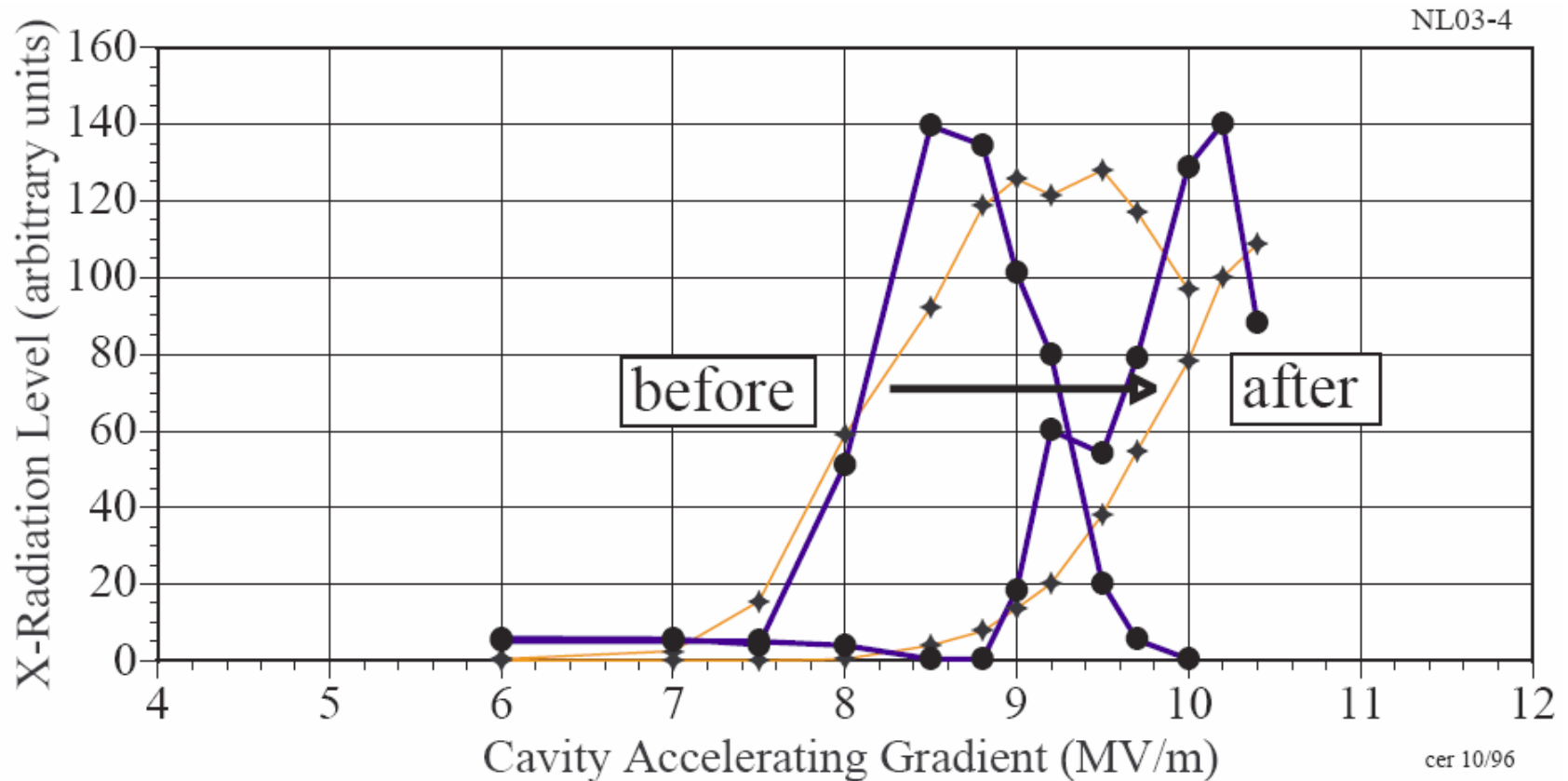
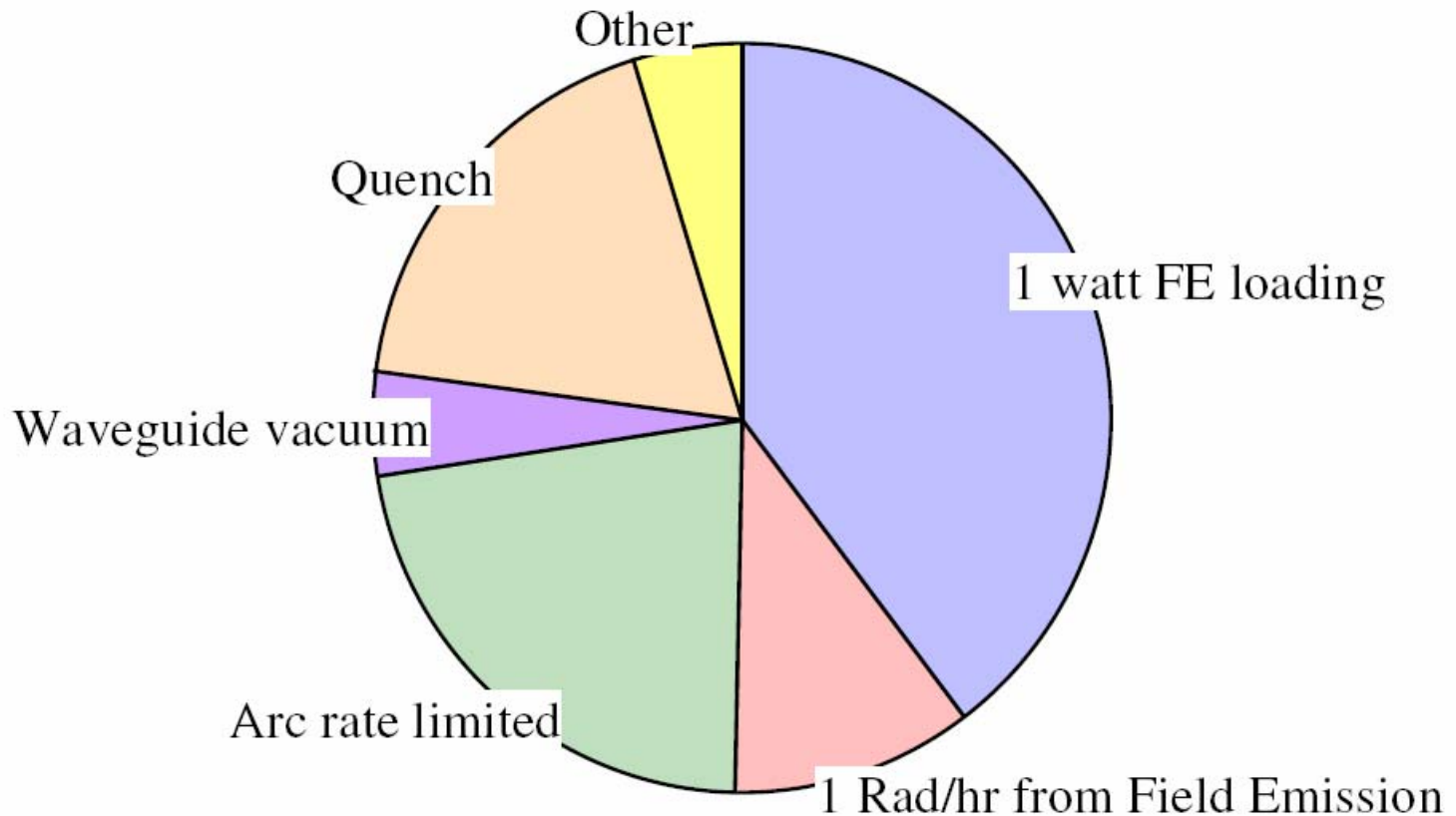


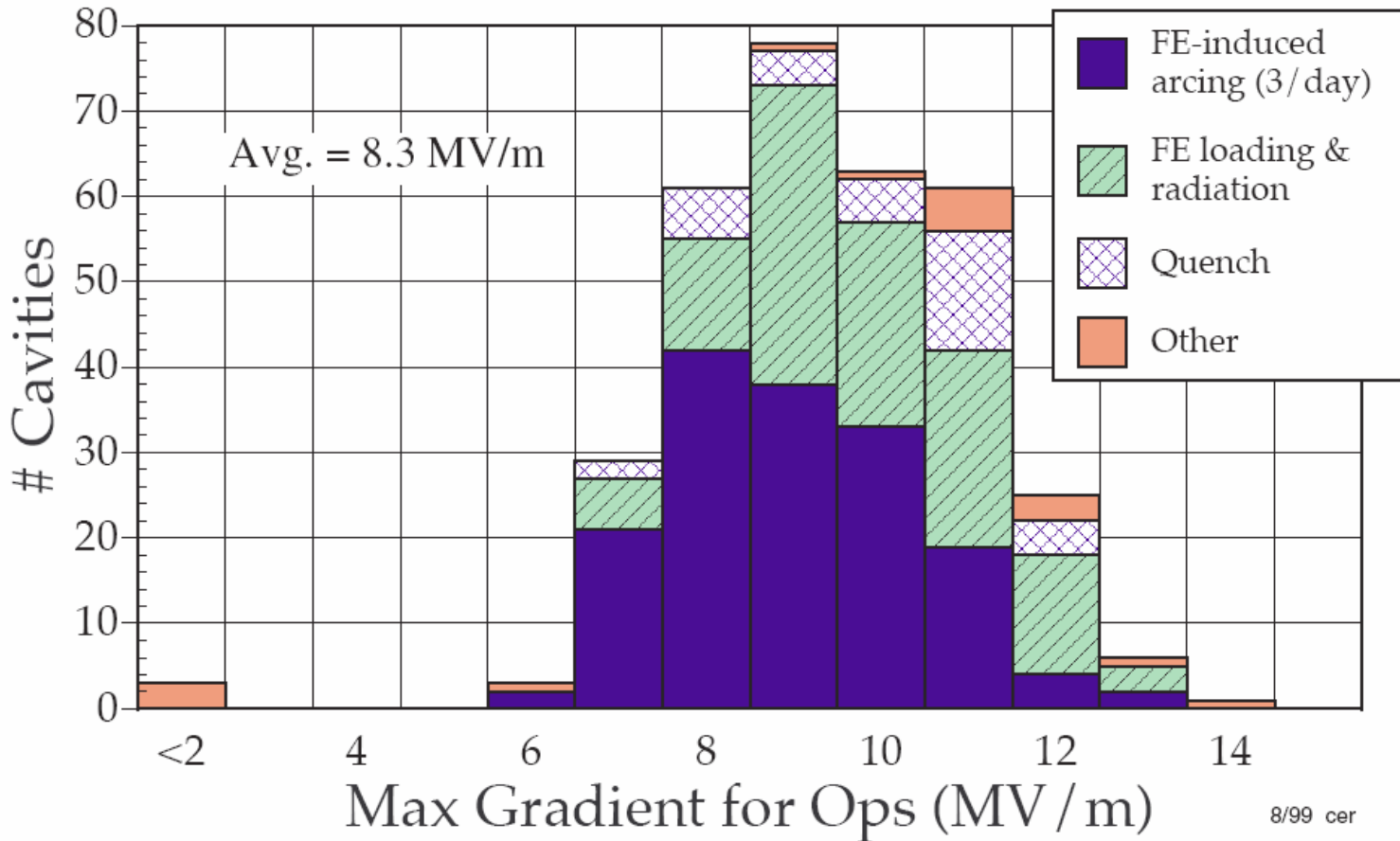
Figure 1. Radiation reduction with He processing.

Practical Limitations (CEBAF)



Practical Limitations (CEBAF)

Distribution of Maximum Operational SRF Cavity Gradients in CEBAF by Type of Limitation

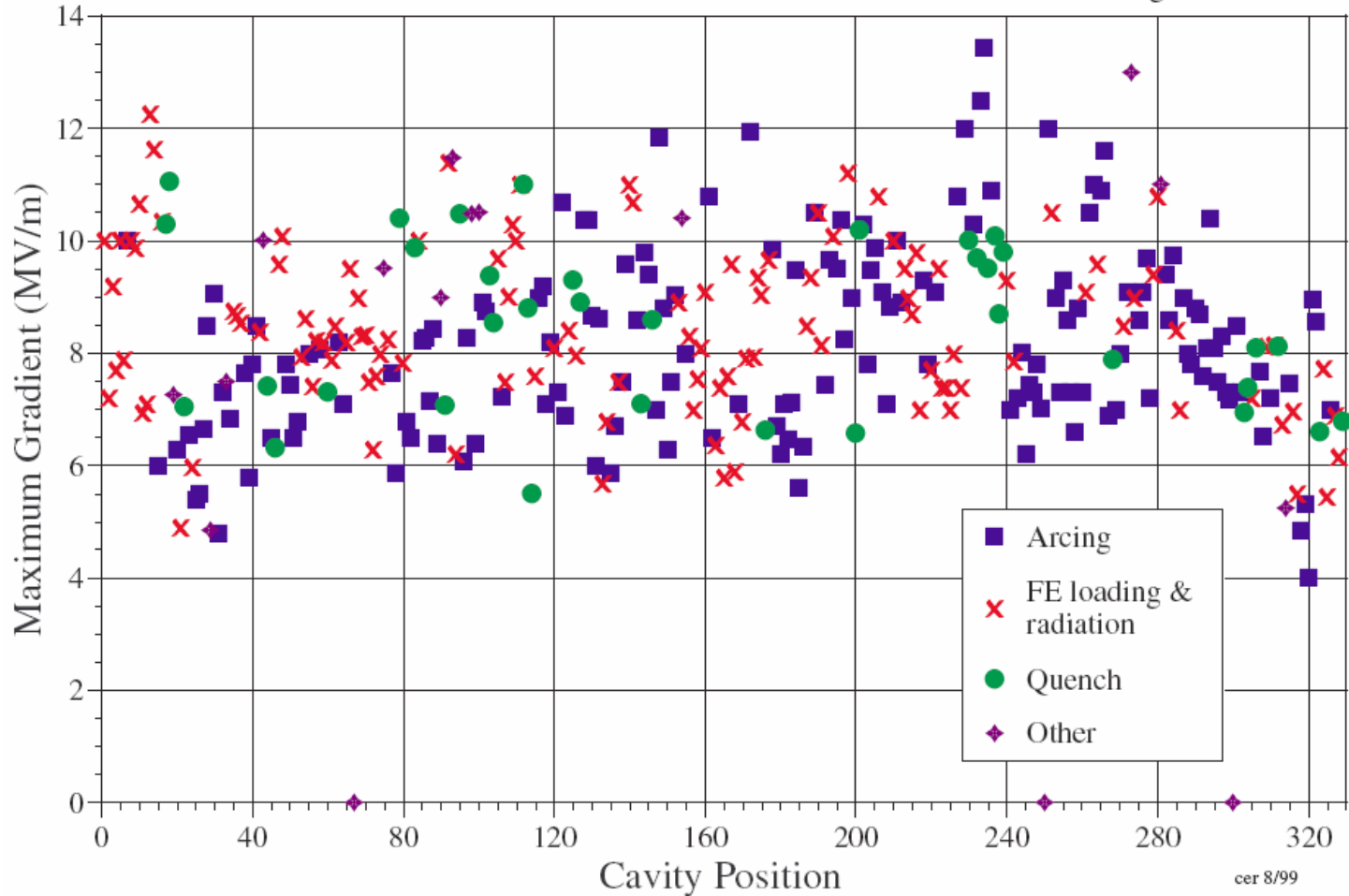


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Practical Limitations (CEBAF)

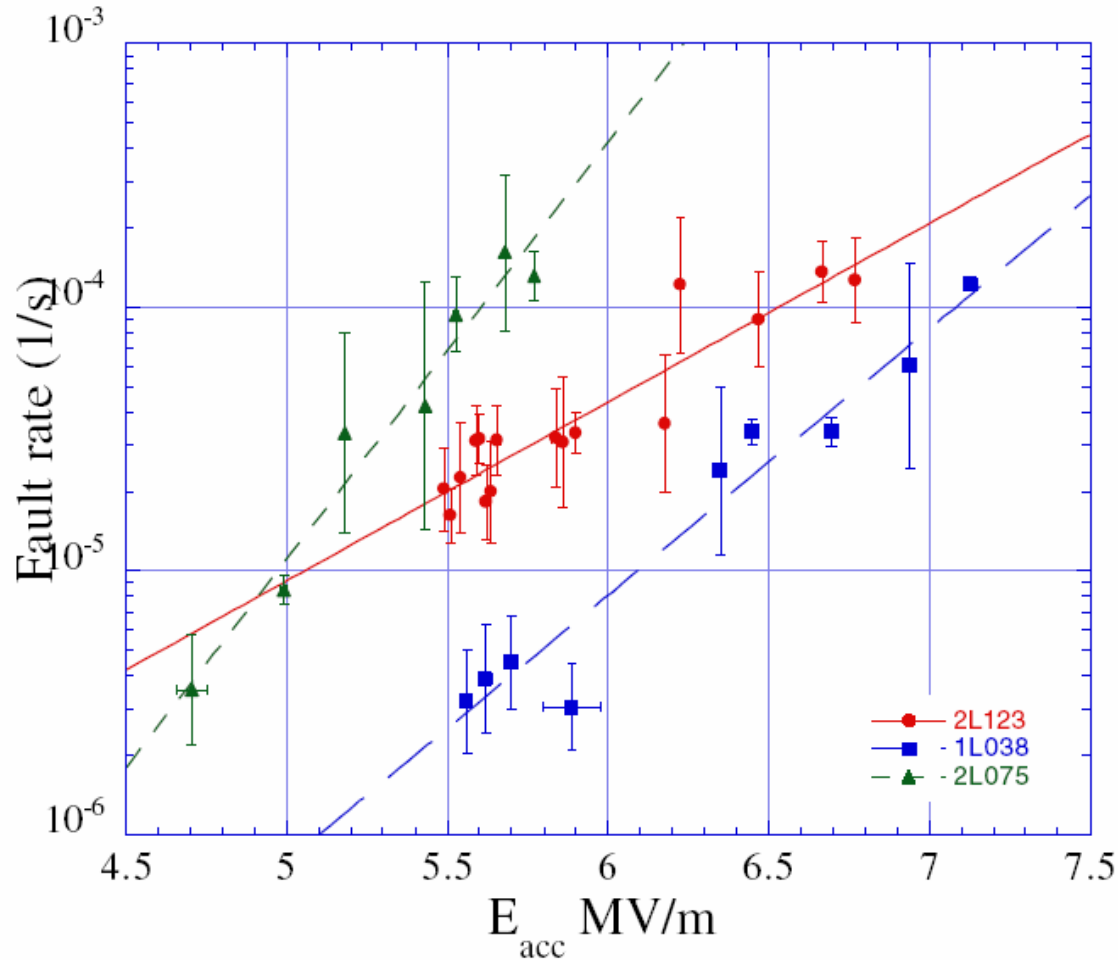
Maximum Operational Gradients by Type of Limitation
CEBAF SRF Cavities

August 1999



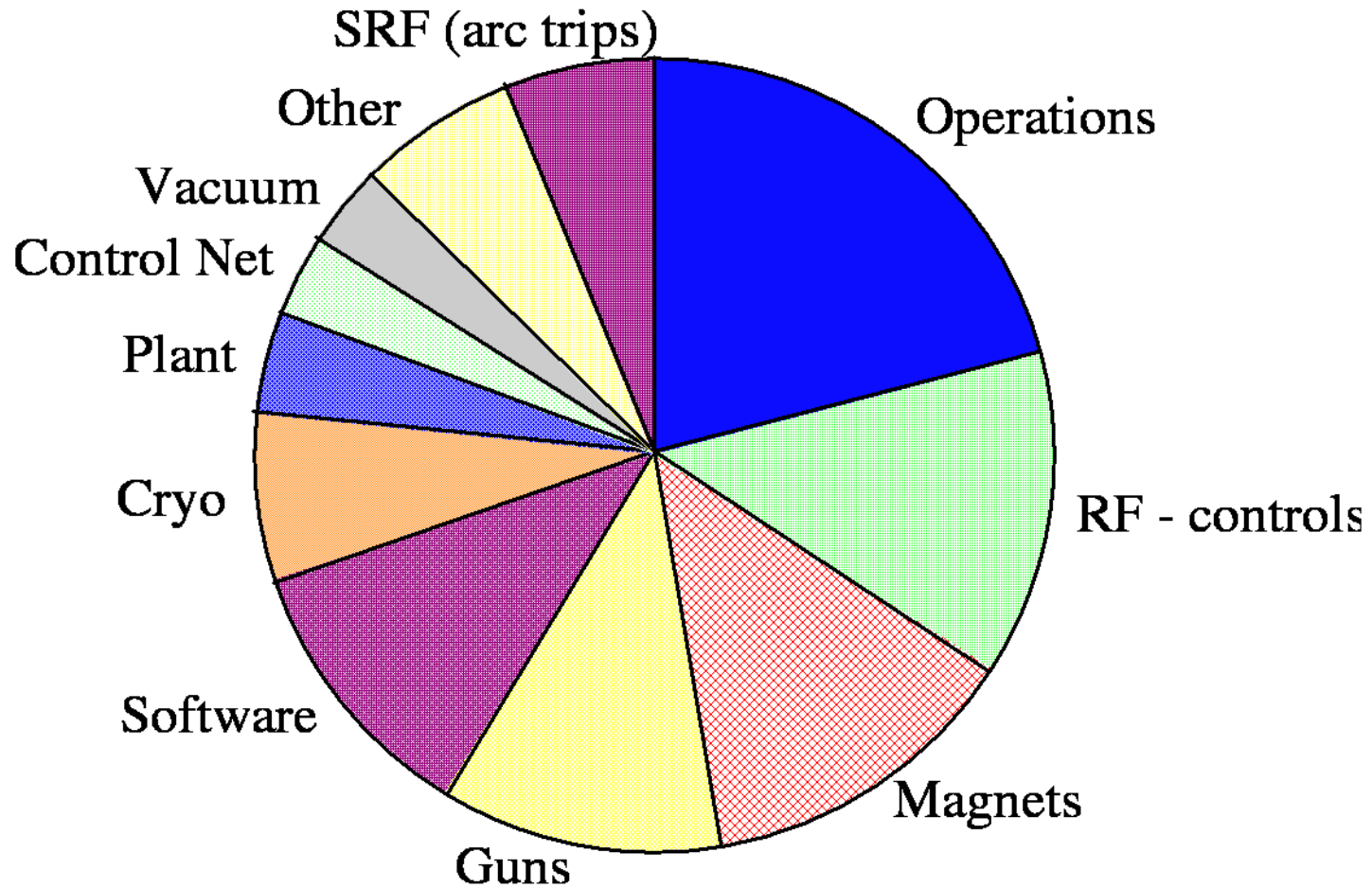
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Practical Limitations (CEBAF)



CEBAF Downtime Distribution

CEBAF Downtime Contribution by System - FY99



Time Evolution of Performance (DESY)

